

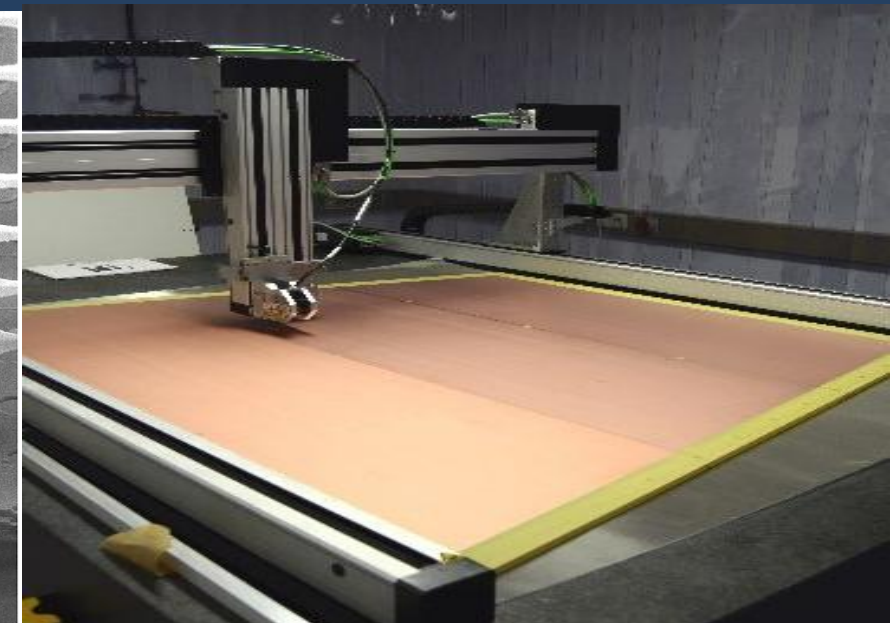
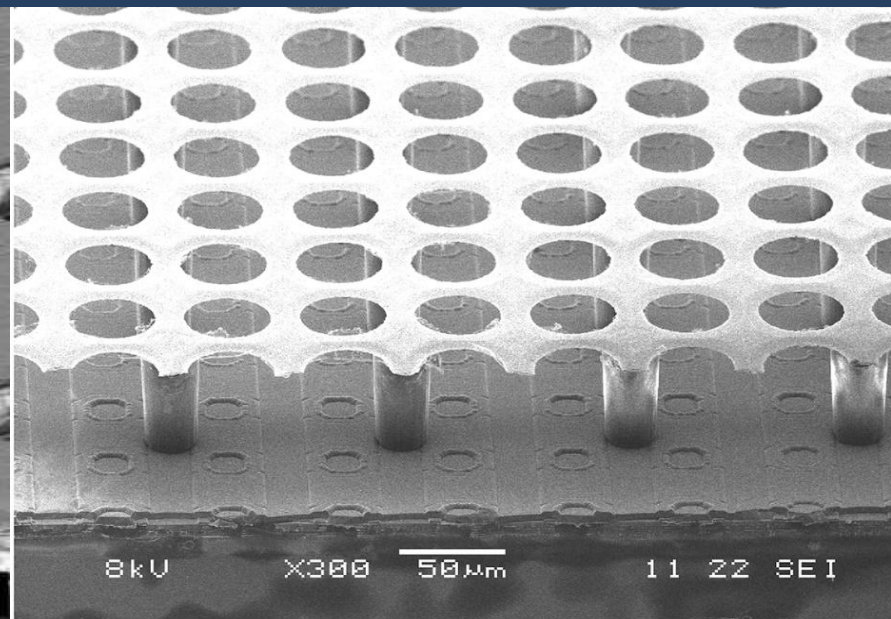
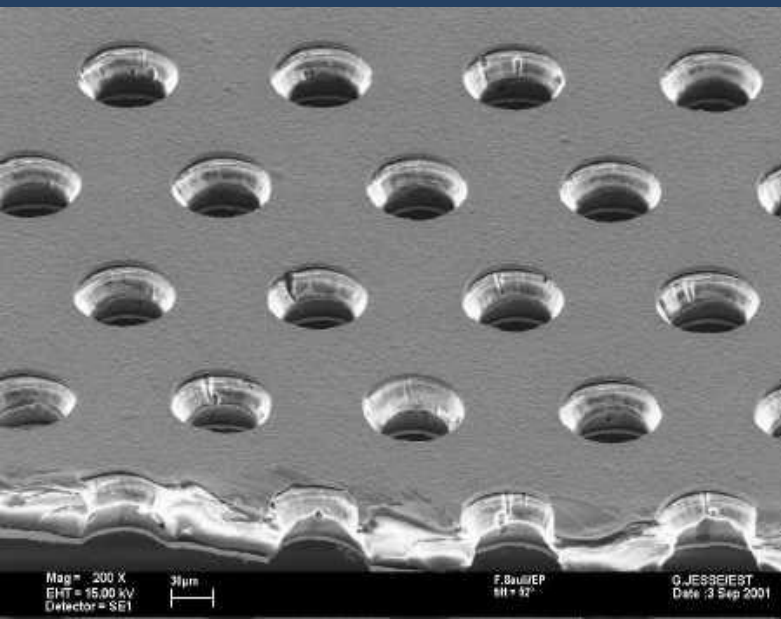


Status and Experience from ATLAS and CMS Muon Detector and Component Production

Kerstin Hoepfner, RWTH Aachen, Phys. Inst. 3A



Terascale Detector Workshop, Bonn, March 2025



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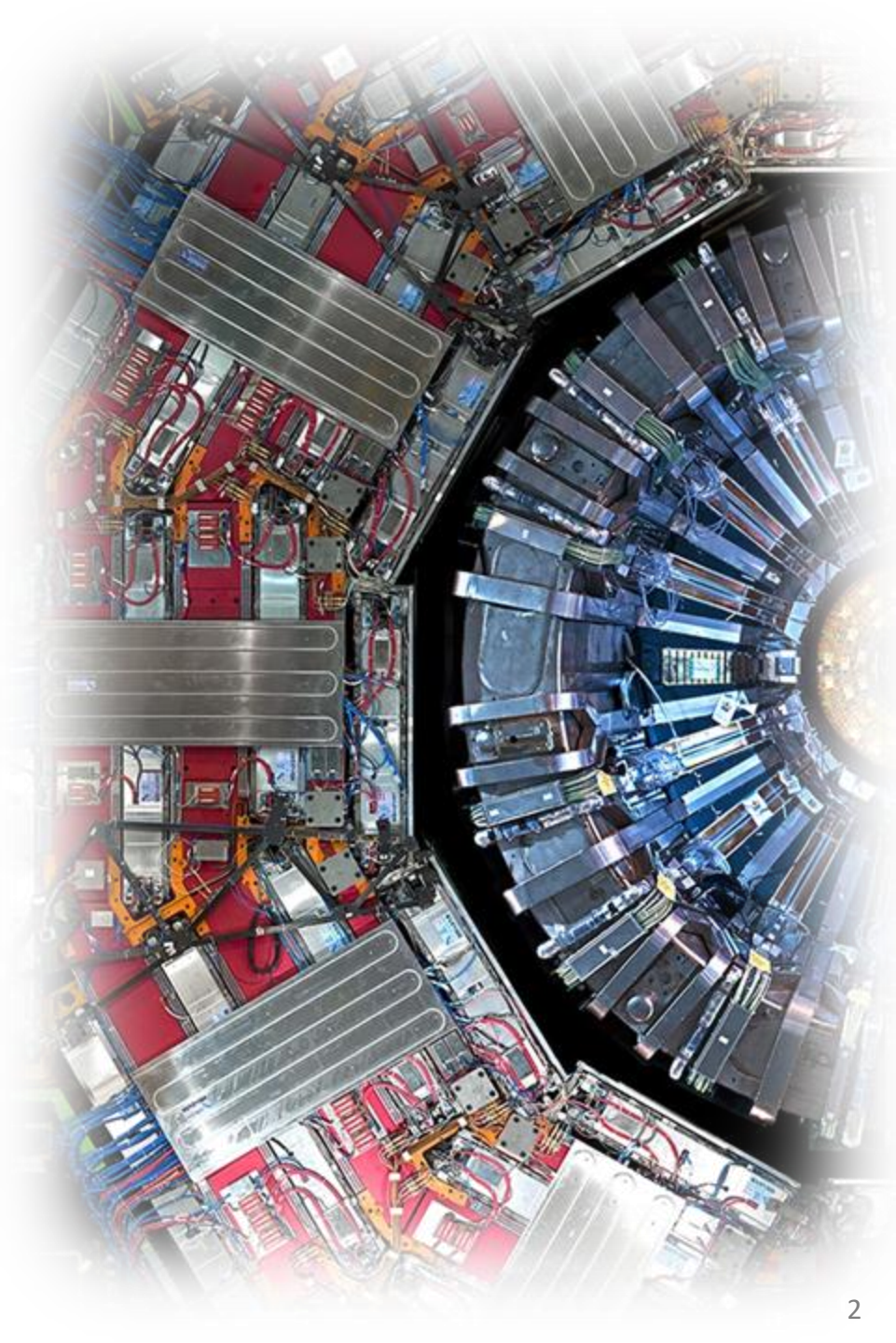
CMS Very Forward Muon Upgrade with
GEM Detectors and iRPC

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ATLAS Muon Upgrade with Micromegas,
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Summary

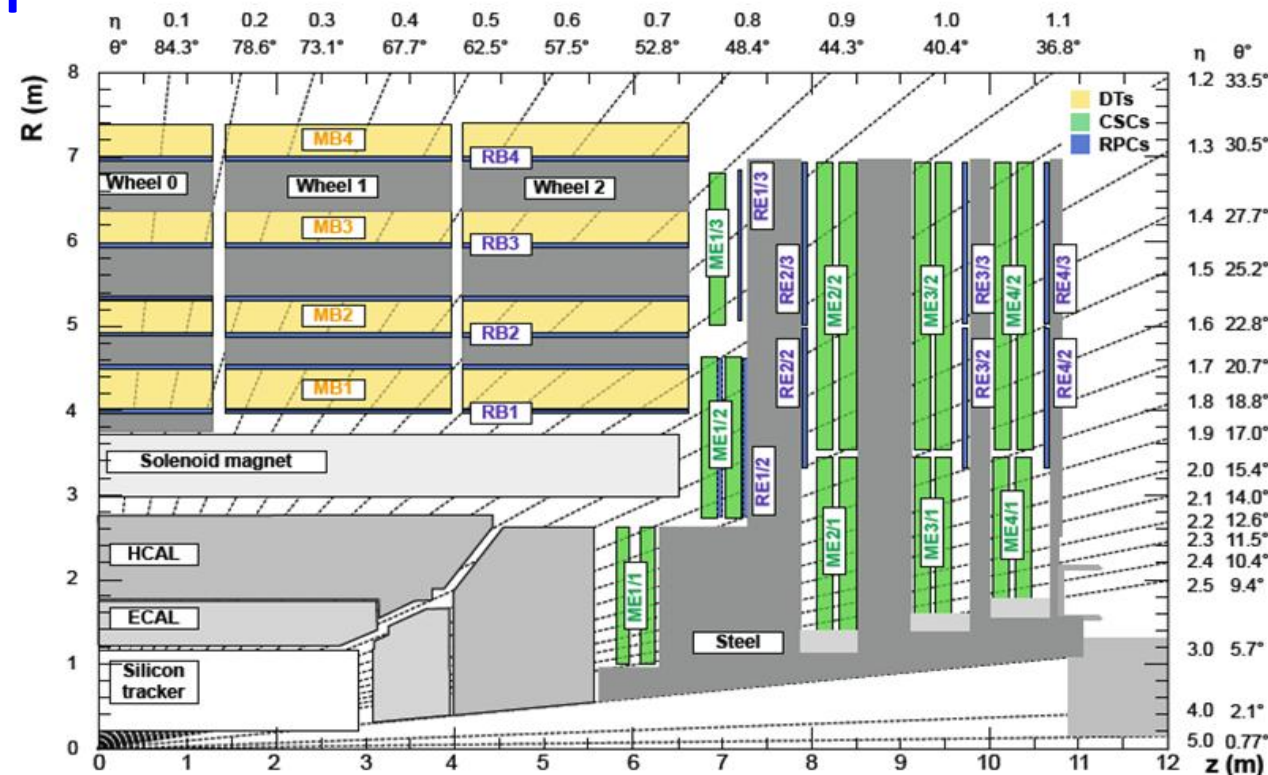




Legacy CMS Muon System

Highly hermetic and redundant muon system

- Drift tubes (DT) in barrel
- Cathode-Strip Chambers (CSC) in endcaps
- RPCs to ensure adequate redundancy
- Trigger coverage up to $|\eta|=2.4$
- Installed in iron return yoke \rightarrow resolution limited by multiple scattering



Detectors and electronics largely installed 2010

Chambers: No indications of aging or detector performance degradation at phase-2 conditions.

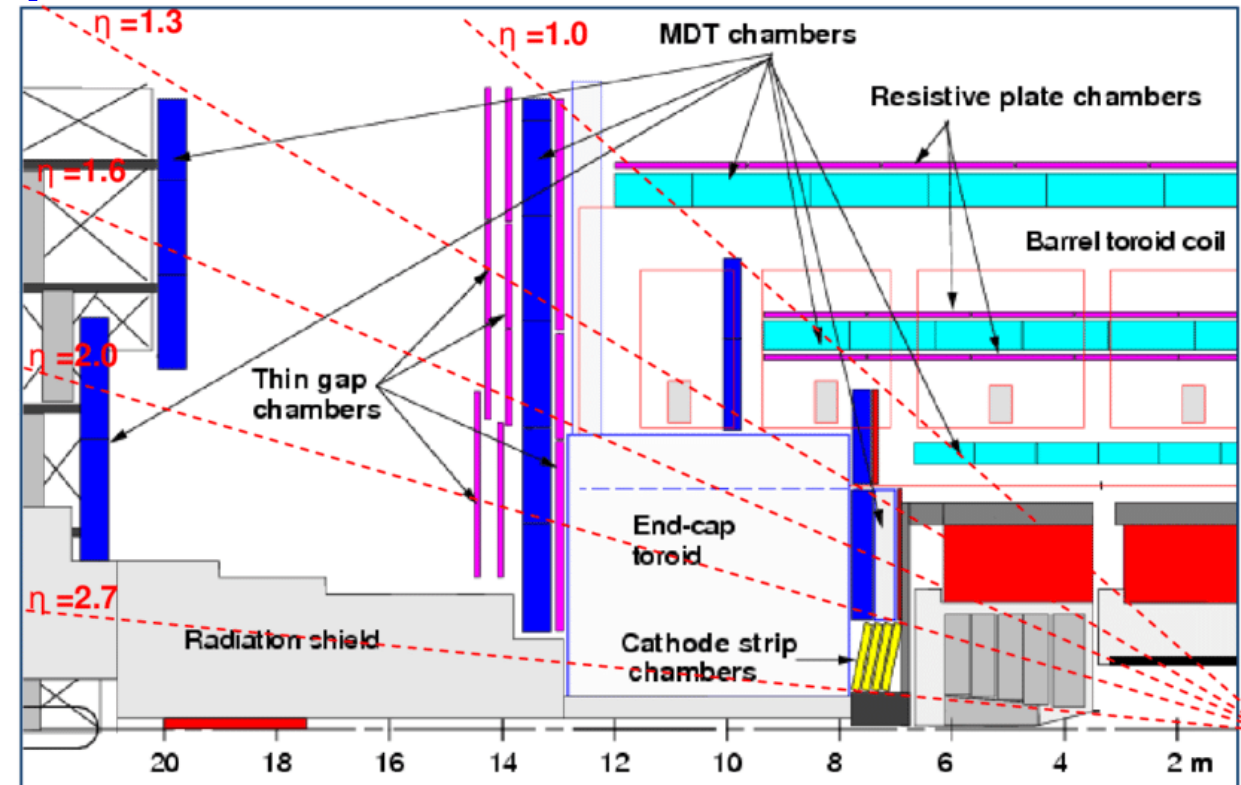
Upgrade: concentrates on **trigger, electronics and additional detectors** for weakly instrumented areas.

Legacy ATLAS Muon System

Very large muon system due to toroid geometry

- Monitored DTs (MDT) in barrel and EC
- Thin-gap chambers (TGC) in endcaps
- RPC in barrel
- CSC in very forward region

Very high resolution, not limited by multiple scattering, less absorption of particles

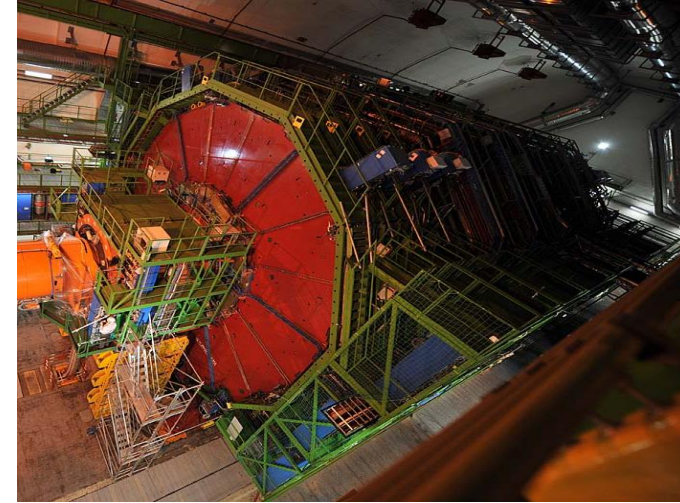
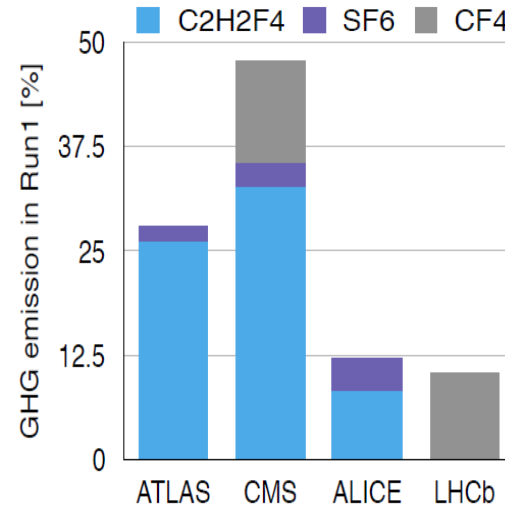
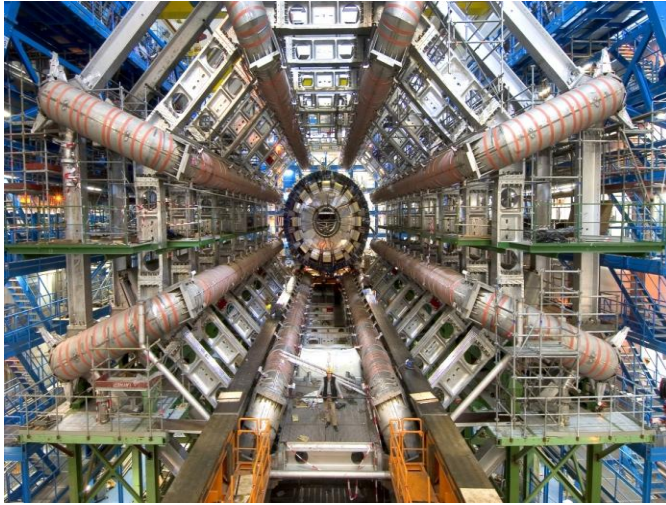


Detectors and electronics largely installed 2010

Chambers: No indications of aging or detector performance degradation at phase-2 conditions.

Upgrade: improve trigger, increase # hits along tracks. Upgrade electronics, additional detectors

F-Gases in ATLAS and CMS



In ATLAS F-gases used in Barrel RPC system

- RPC gas mixture: $\text{C}_2\text{H}_2\text{F}_4 + \text{iC}_4\text{H}_{10} + \text{SF}_6$ (94.7+5+0.3)%

In CMS F-gases used in two muon detector systems: CSC (Endcap) and RPC (Barrel + Endcap)

- RPC gas mixture: $\text{C}_2\text{H}_2\text{F}_4 + \text{iC}_4\text{H}_{10} + \text{SF}_6$ (95.2+4.5+0.3)%
- CSC gas mixture: $\text{Ar} + \text{CO}_2 + \text{CF}_4$ (40+50+10)%

Why $\text{C}_2\text{H}_2\text{F}_4$ and SF_6 in RPC gas mixture? to guarantee: **Stable detector performance** (high efficiency, large avalanche stability plateau, prevention against ageing effects) **for 10 years of LHC operation**

Solution for **today: Recirculation & recuperation**

But Global Warming Potential (GWP)
 $\text{C}_2\text{H}_2\text{F}_4 = 1000$
 $\text{CF}_4 = 7400$
 $\text{SF}_6 = 22800$

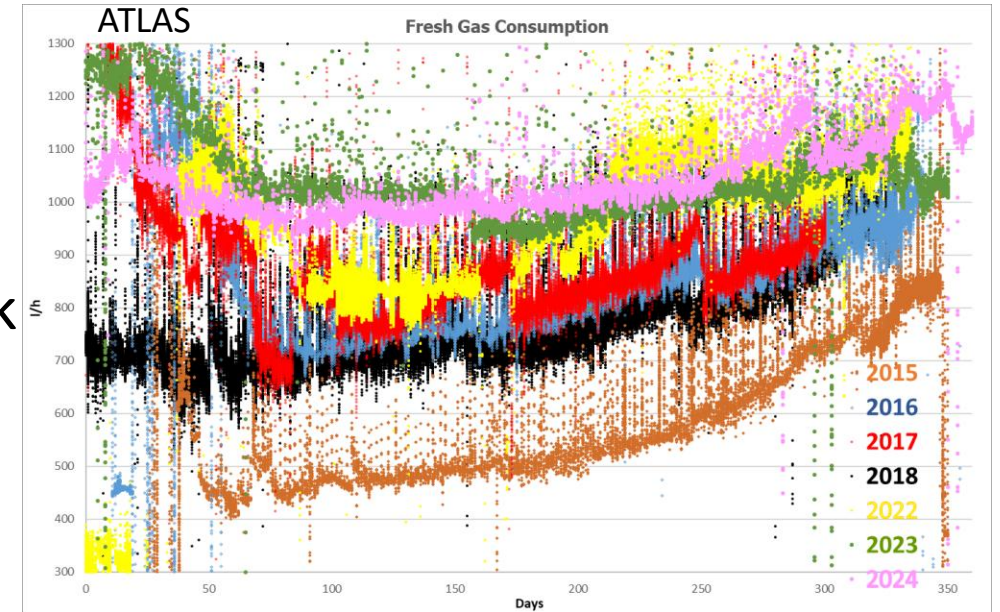
Gas Leaks in Legacy RPCs (ATLAS/CMS)

Legacy RPCs developed gas leaks

Caused by different types of **material aging**

- CMS polyethylene pipes becoming brittle and crack
- ATLAS cracks develop in polycarbonate moulded in/outlets
- Mechanical stress on gas connectors

Sealing gas pipe from inside (ATLAS)



Multiple **repair campaigns** during shutdowns.

- **Reduce** mechanical stress
- **Replace, bypass or seal** gas tubes
- **Reduce** gas distribution multiplicity

Chamber access difficult. In CMS barrel needed to extract entire DT + RPC. CMS EC RPCs are not leaking.

For Future: Reduce CF_4 in CSC (CMS)

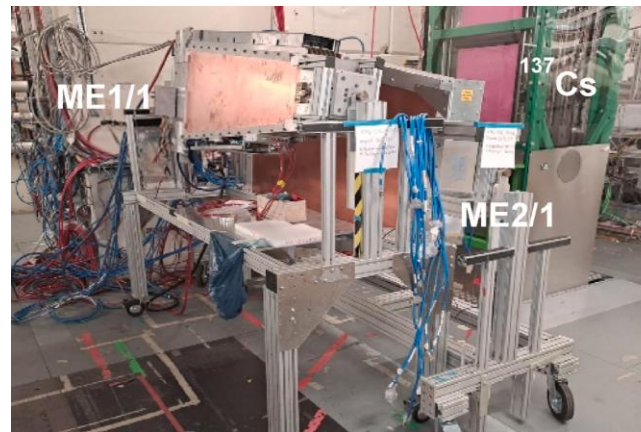
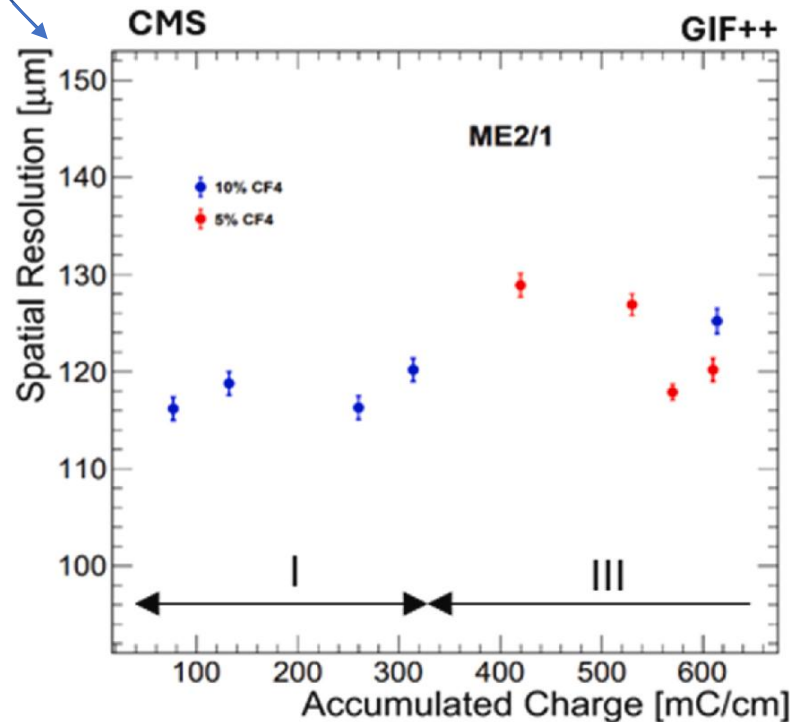
Attempts to reduce fraction of gas with high GWP,

e.g. CMS CSC CF_4 10% \rightarrow 5%

No performance degradation (spatial resolution, dark current) seen at aging tests at GIF++ up to 800 mC/cm

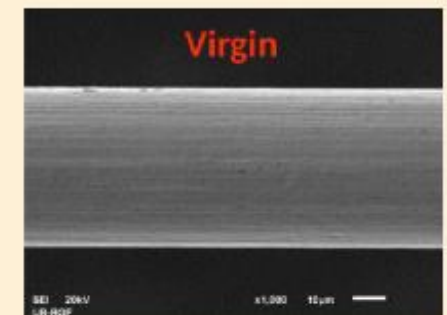
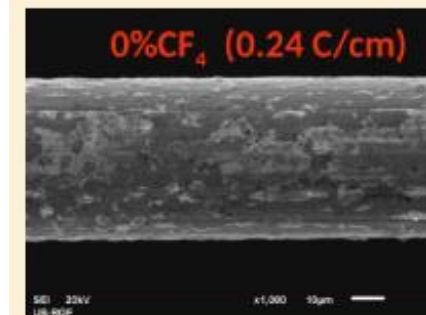
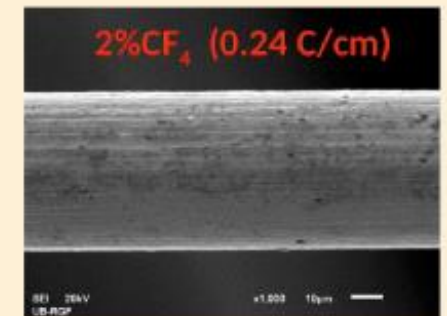
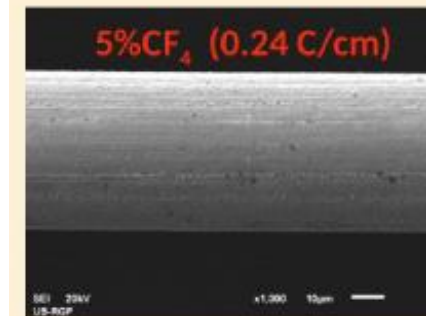
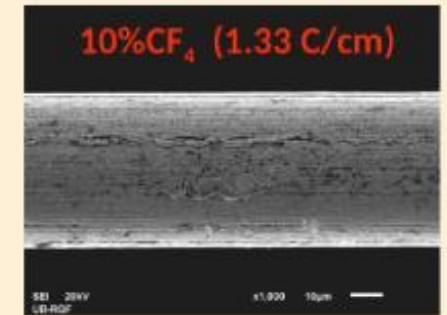
- Anode deposits clearly seen for 2% and less

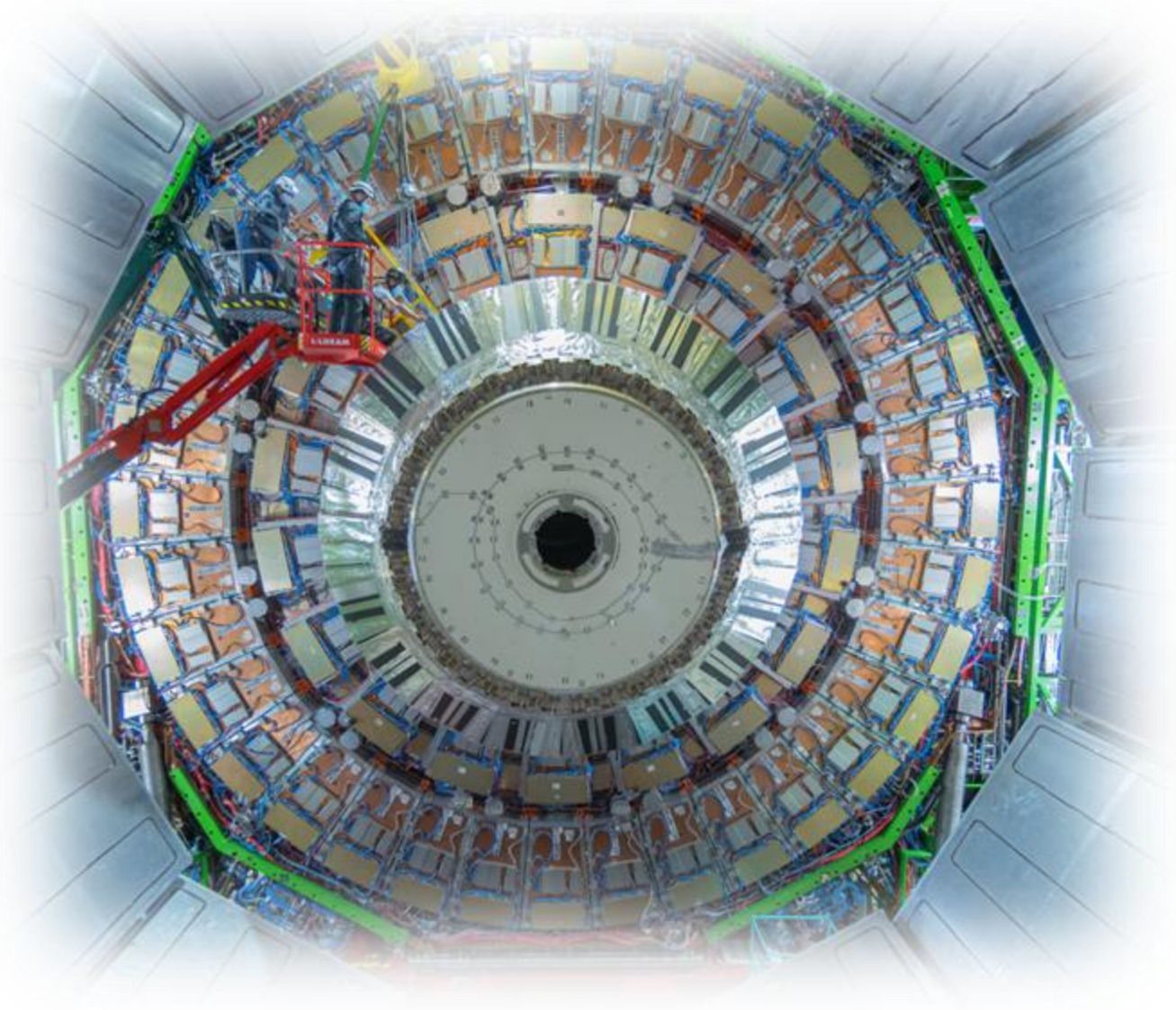
CSC chambers contain wires. Work in avalanche mode.



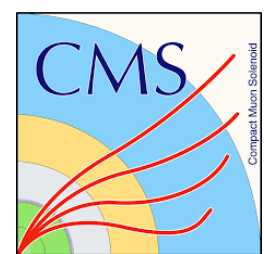
Tests of CSC chambers with varying CF_4 fraction at GIF++ 10% (I), 2% (II), 5% (III), 0% (IV)

Surface morphology of anode wires
Secondary electron images - 3D
(University of Belgrade)

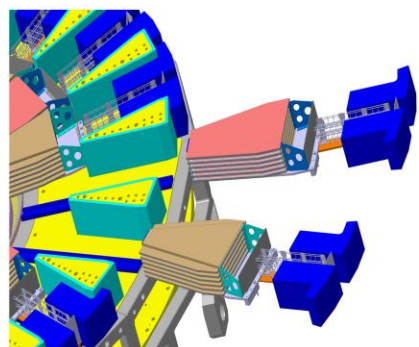




CMS Muon Forward Upgrade with GEMs and improved RPCs



CMS Upgrade of Forward Muon Region



High Rates up to 150 kHz/cm²!

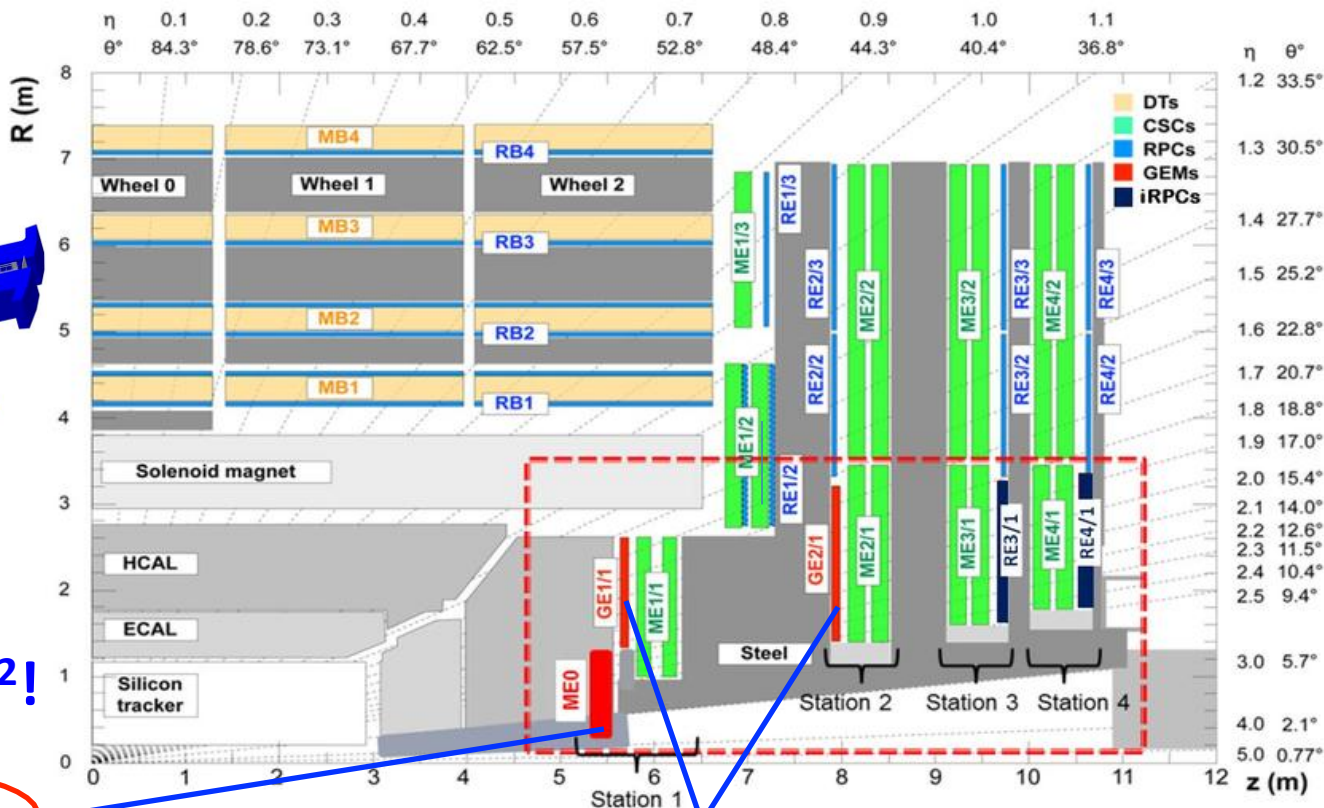
MEO:

- Triple GEM technology
- Last station of HGCal
- 6 layers form one stack
- $2.0 < |\eta| < 2.8$
- Under construction

Triple GEM

GE1/1 and GE2/1:

- Triple GEM technology
- For 1st and 2nd EC station where bending is strong
- Two layers per trapezoidal chamber
- $1.55 < |\eta| < 2.1$
- GE1/1 operational, GE2/1 postponed

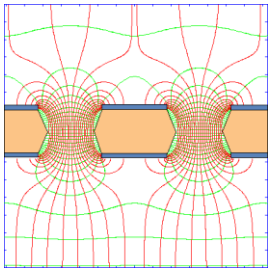


Thin-gap RPC

iRPC:

- Thinner RPC technology
- For 3rd and 4th EC station where bending is weaker
- Timing resolution 0.5 ns
- $1.9 < |\eta| < 2.5$
- Max rate 700 Hz/cm²
- Installed YETS 2024/2025

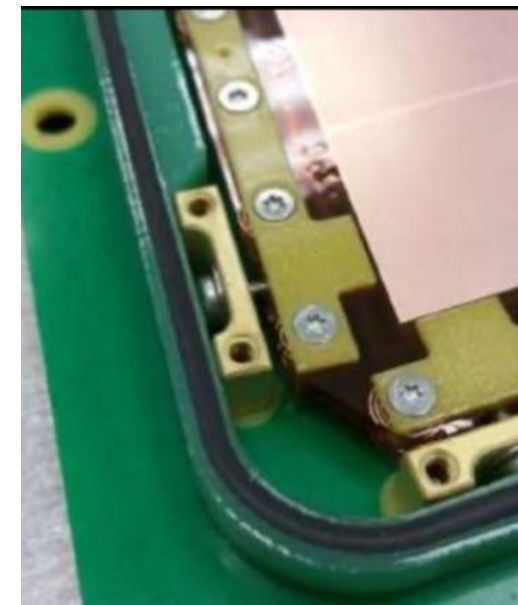
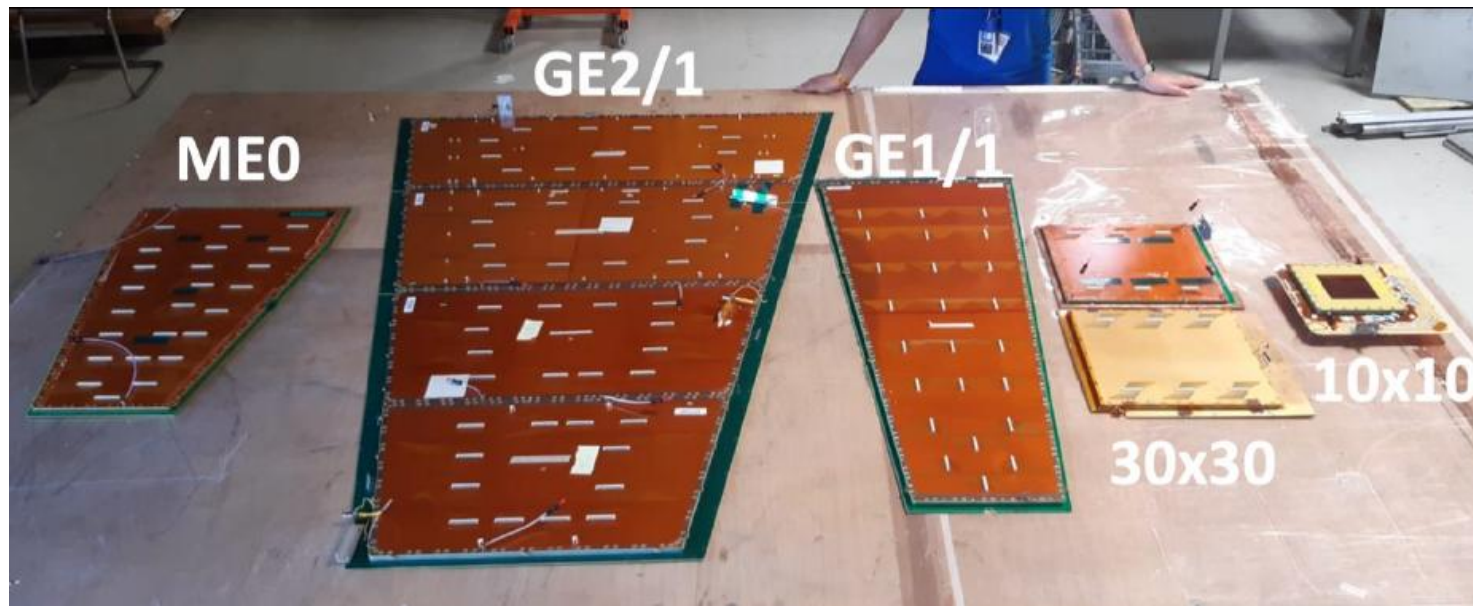
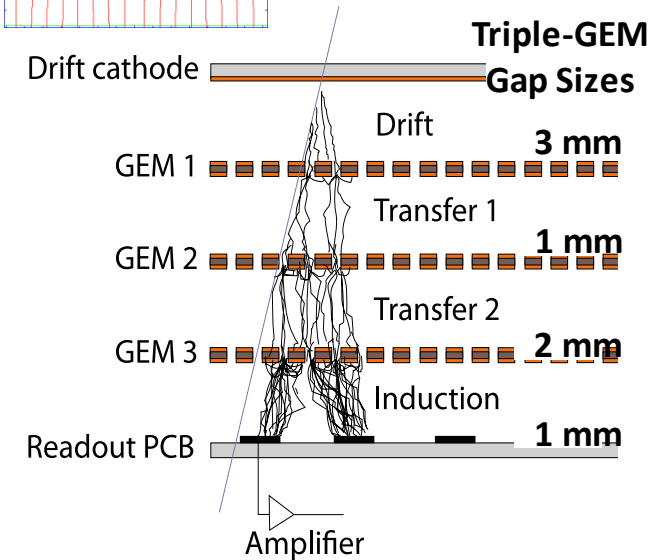
Gas Electron Multiplier (GEM)
Micro-pattern gaseous detectors (MPGD)



CMS Triple-GEM Technology

CMS triple-GEM common design:

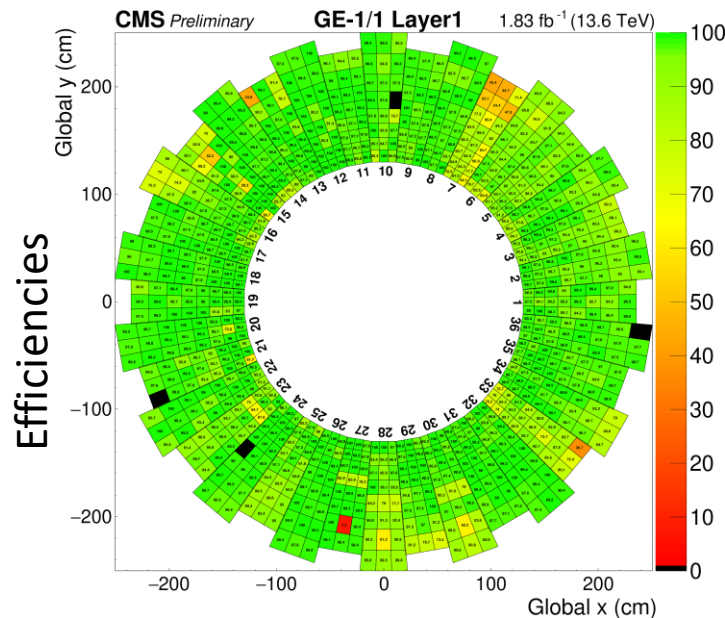
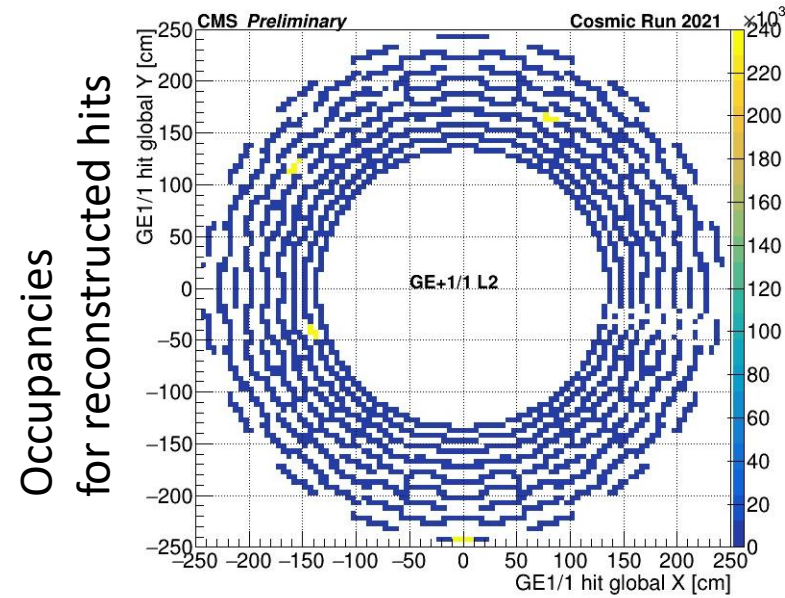
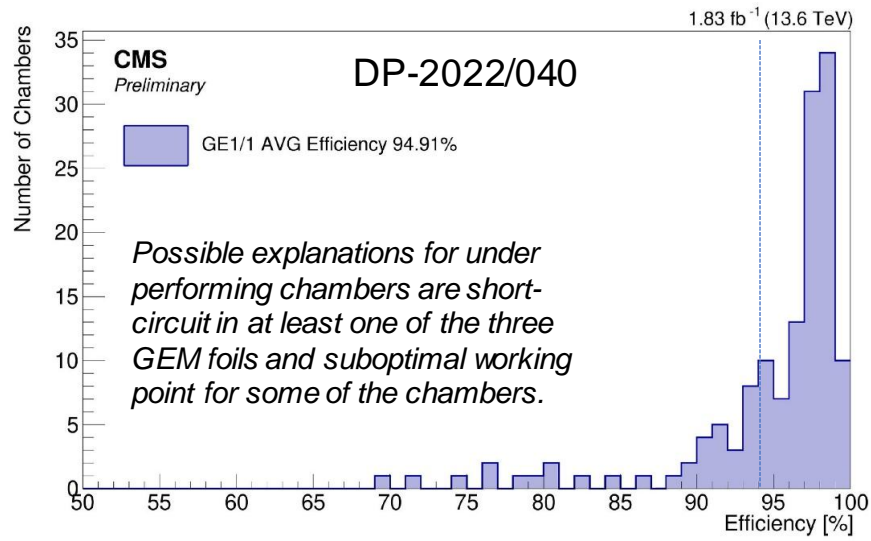
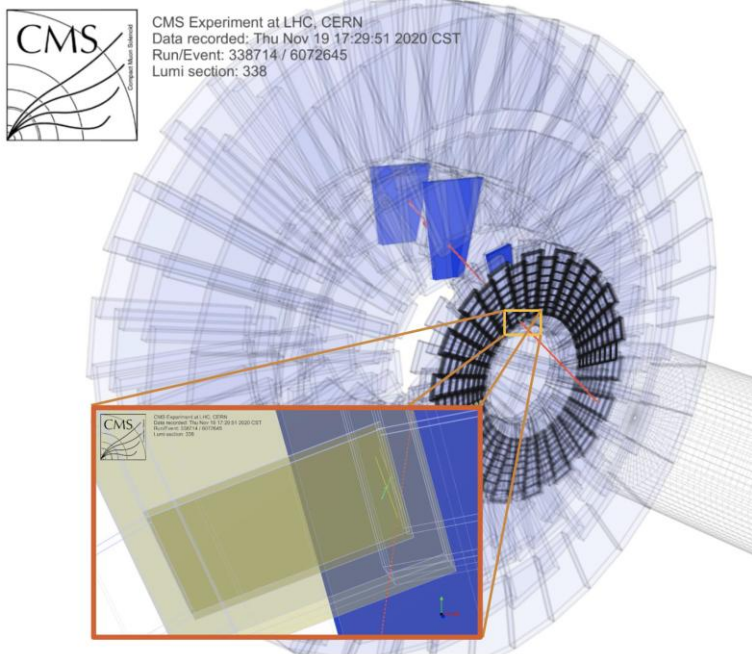
- Three detector projects based on same triple-GEM technology and same material. Slight design adaptations per station.
- GEM configuration: 3 (drift)/1/2/1 mm
- Gas mixture: 70% Ar + 30% CO₂
- Max bkgr rates: few kHz/cm² (GE/2/1) to 150 kHz/cm² (ME0)
- Nearly 700 detectors: 600 m² of GEM foils for 1.5 M RO channels



Self-stretching assembly technology developed by CMS GEM for fast mass production (no gluing!)

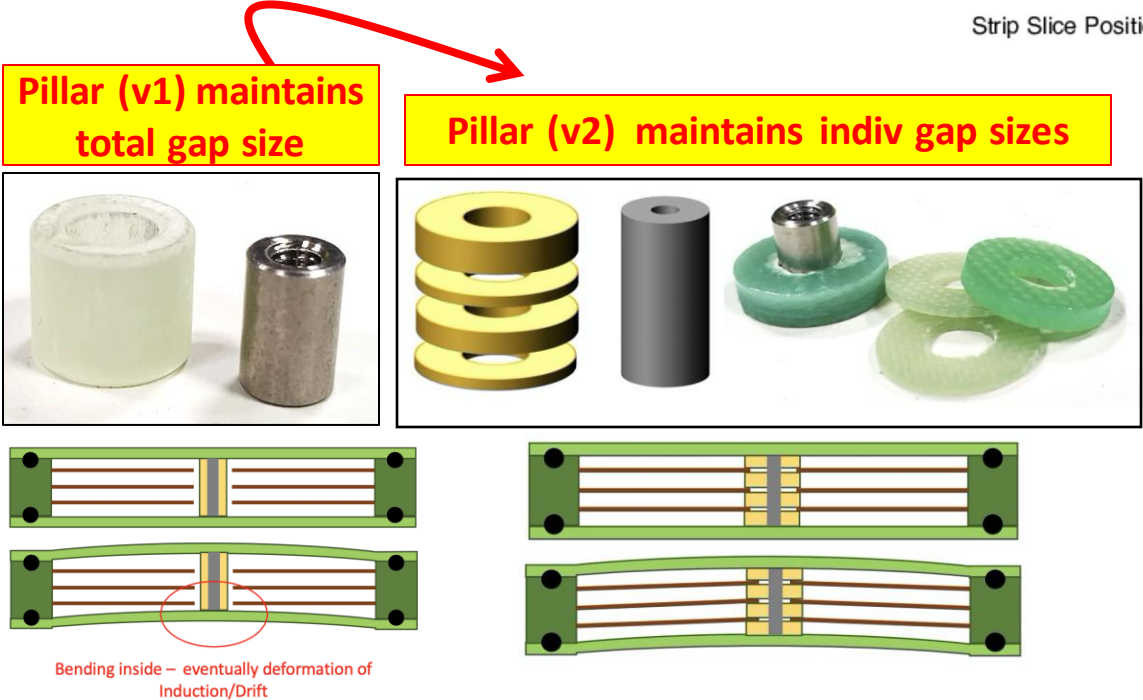
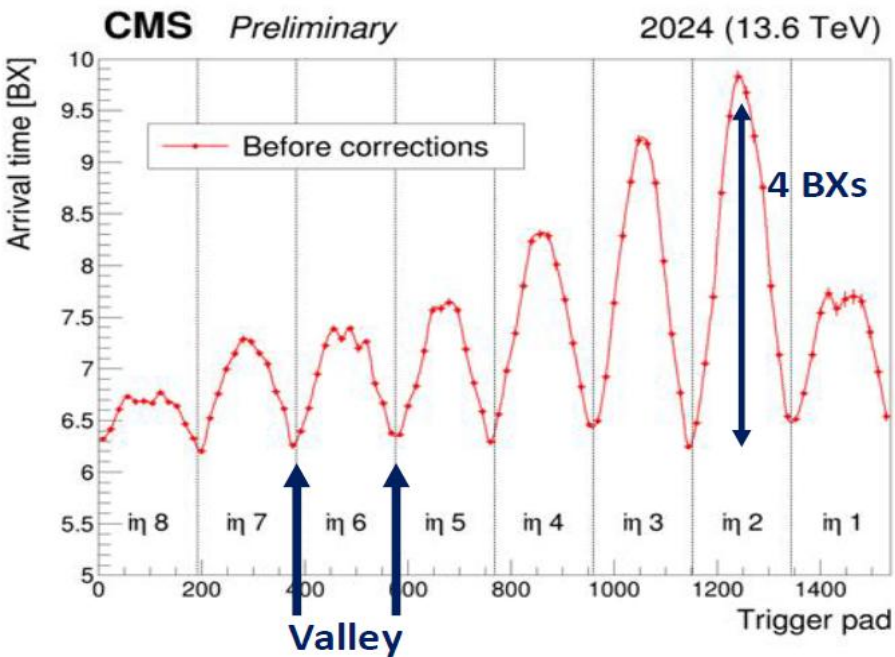
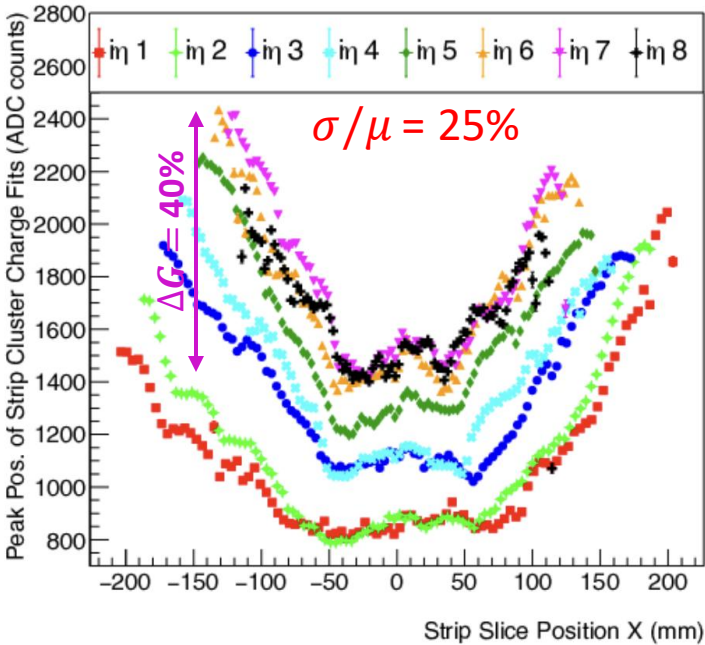
GE1/1 Operates as Part of CMS

Installed in LS2. Routine operation since start of Run-3

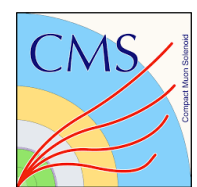


Importance of GEM Gap Size

- GE1/1 in **spacerless design** to reduce dead area. GEM foils stretched (8-10 cN/m applied at ~50 positions along the foil stack)
- Gain Uniformity showing **deviations up to 40%** → Drift & RO PCBs **bend** and deform gas gaps inside detector
- Effects seen in Detector Occupancy & Efficiency & **Timing**



→ Use central pillars with inner rings in ME0 station

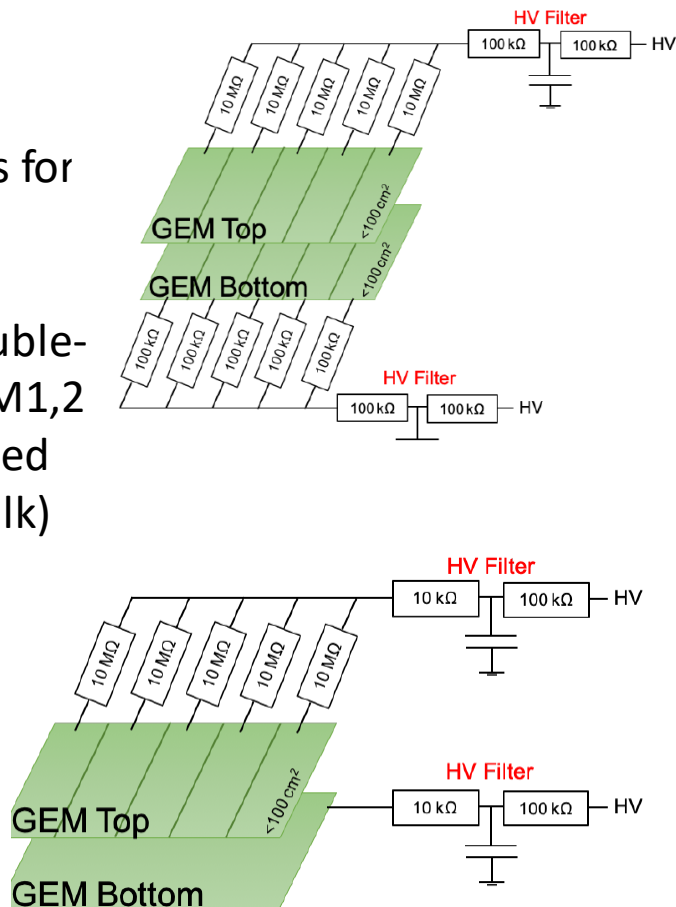


Present Focus – GEM ME0

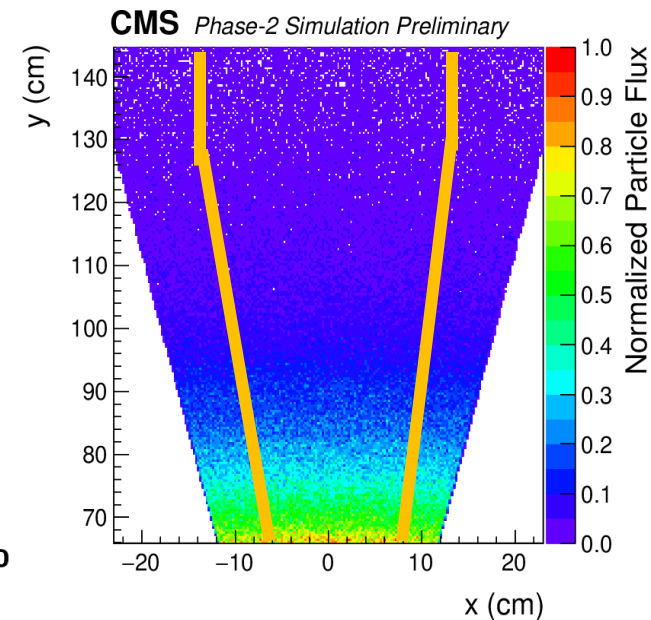
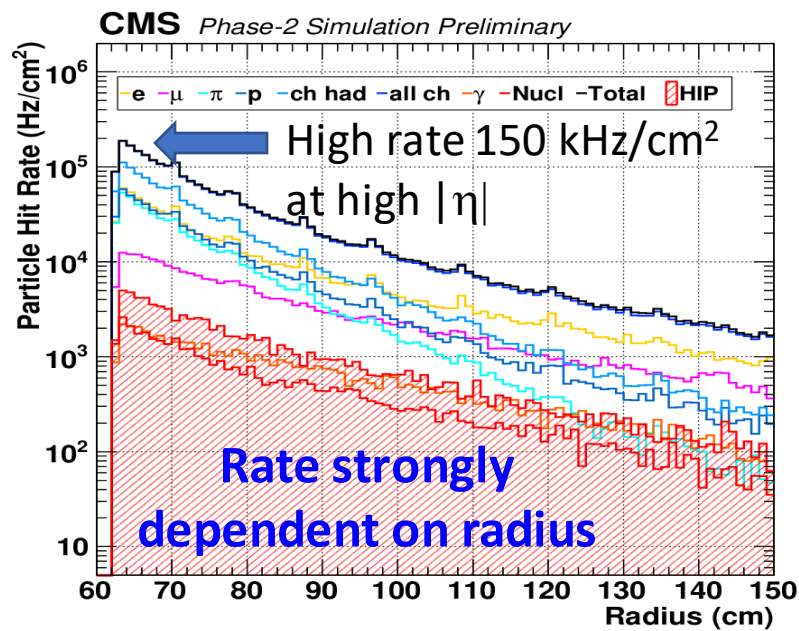
Optimization of HV segmentation to mitigate discharge propagation

GE1/1 single-segmented foils for all 3 stages

GE2/1, ME0 double-segmented GEM1,2
Single-segmented GEM3 (less x-talk)



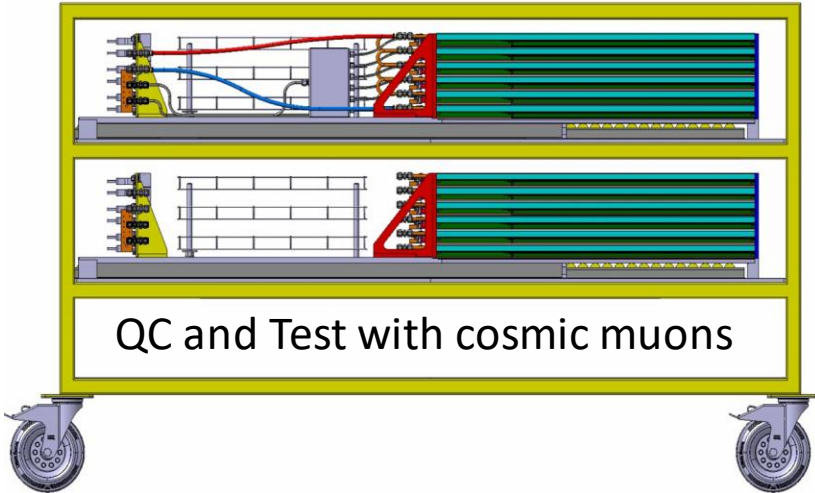
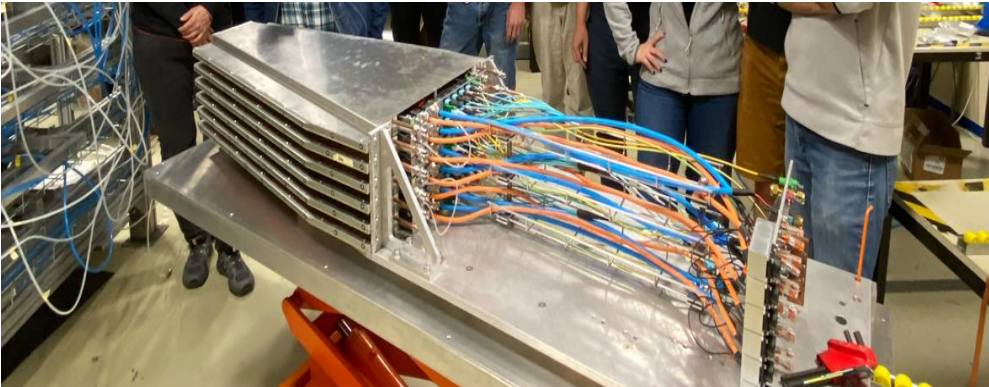
Switch to **radial** HV segmentation for similar flux on all segments. **Each segment sees same gradient** of particle rate. Allows **uniform voltage compensation** of the entire detector.



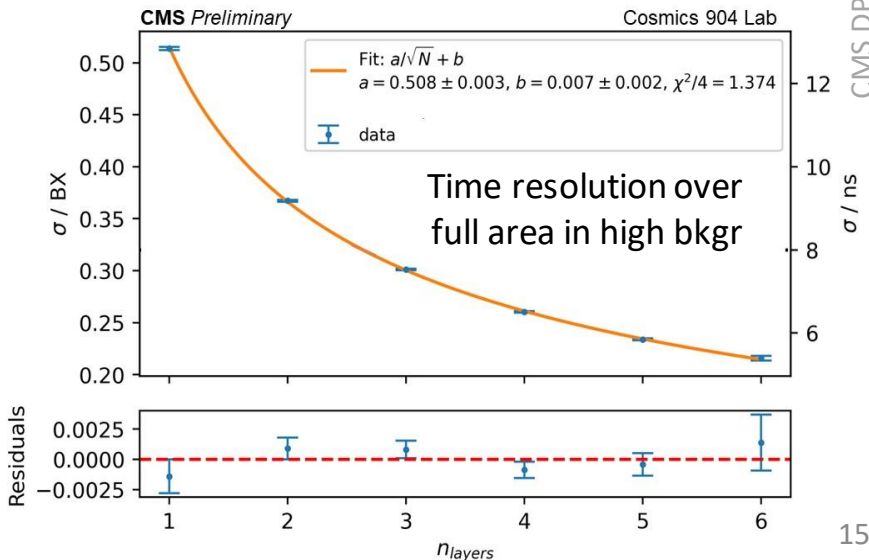
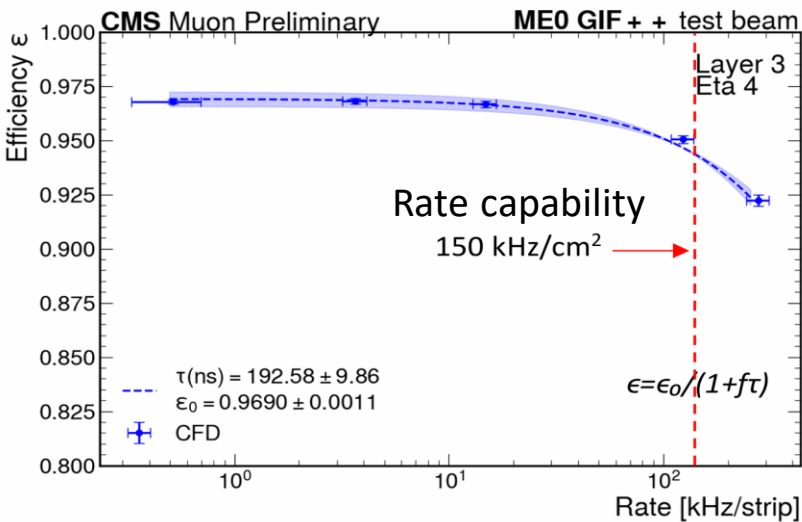
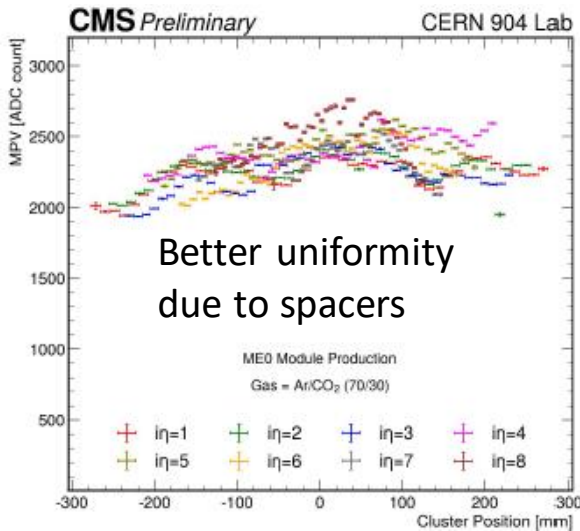
ME0 - Status

Challenge: build in 2 years 36 + 2 stacks = 228 + 3 chambers

Spring 2024: First stack with 6 chambers equipped with latest electronics. Before stack assembly tested each chamber individually.

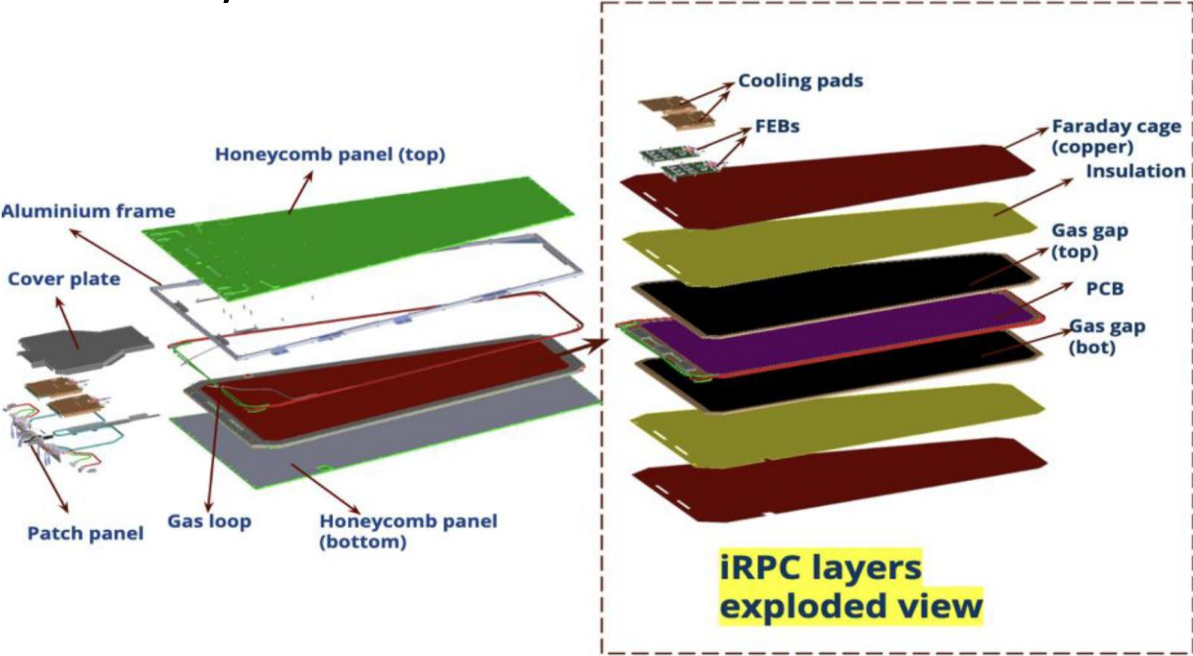
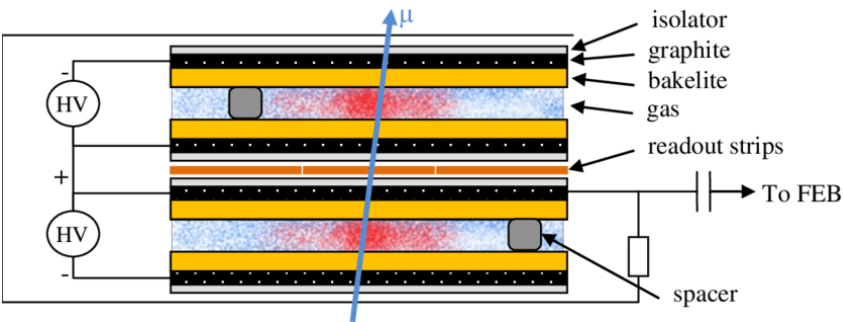


Stack performance and time resolution in muon test beam in presence of high background (GIF++). **Satisfies TDR requirements**



Improved iRPC for CMS Muon Forward

- RPC = **Fast** parallel-plate detector with **high resistivity** electrodes operated in avalanche or streamer mode (CMS = avalanche)
- In 2010 no RPC in very forward because of rate capability
- For upgrade improved rate capability: reduced gap size, low-resistivity bakelite

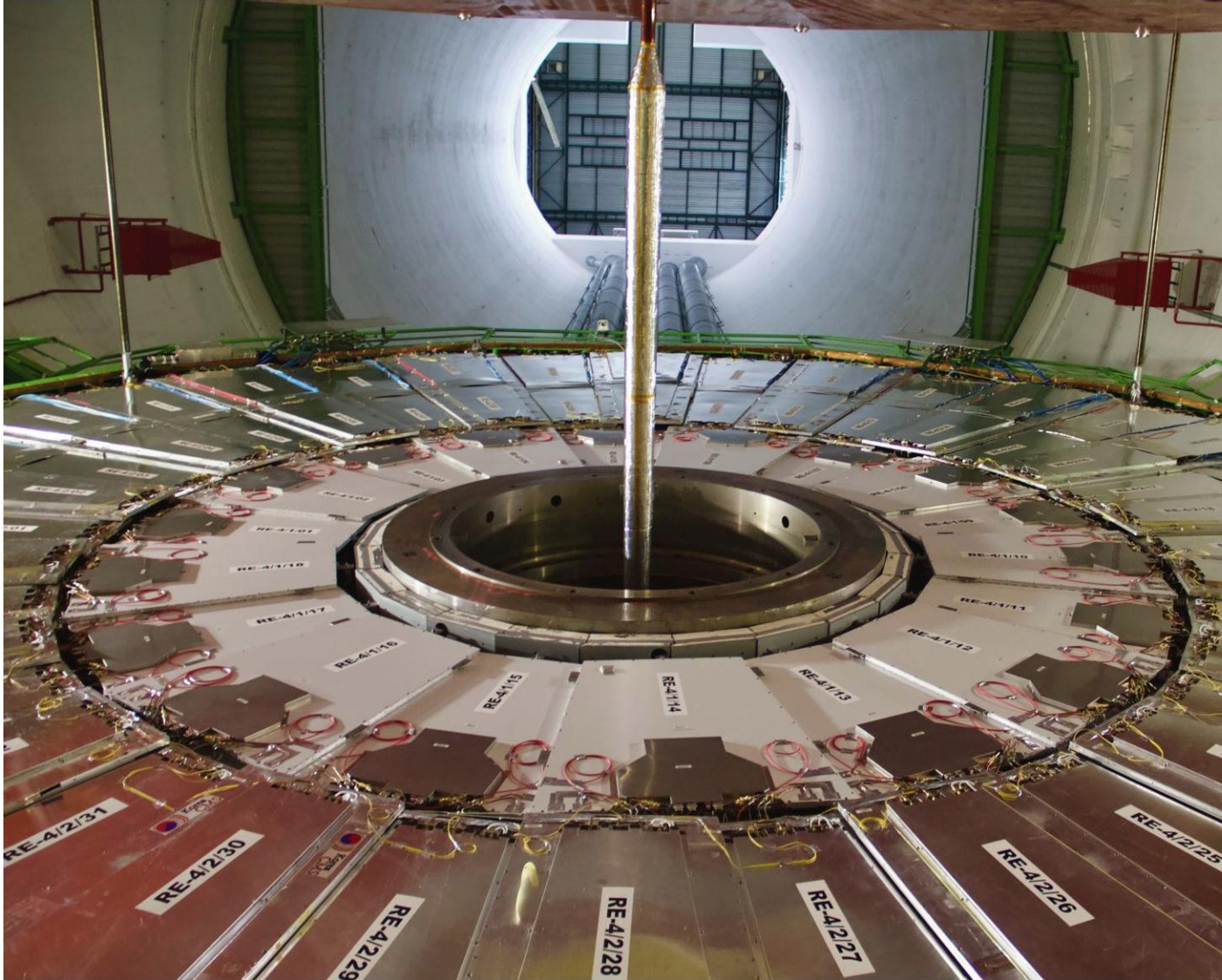


	RPC	iRPC
HPL thickness (mm)	2	1.4
Number of gas gaps	2	2
Gas gap thickness (mm)	2	1.4
Resistivity (Ωcm)	$1 - 6 \times 10^{10}$	$0.9 - 3 \times 10^{10}$
Charge threshold (fC)	150	30 - 40
Space resolution in η (cm)	20 - 28	1.5
Space resolution in ϕ (cm)	0.8 - 1.9	0.3 - 0.6
Intrinsic timing resolution (ns)	1.5	0.5

iRPC FEB is equipped with low noise front-end electronics that can detect signals with a charge as low as 30 fC

2d readout for iRPC.

iRPC installed in last YETS 24/25





ATLAS Muon Upgrade with „New Small Wheel“ and new barrel RPCs

ATLAS New Small Wheel (NSW)

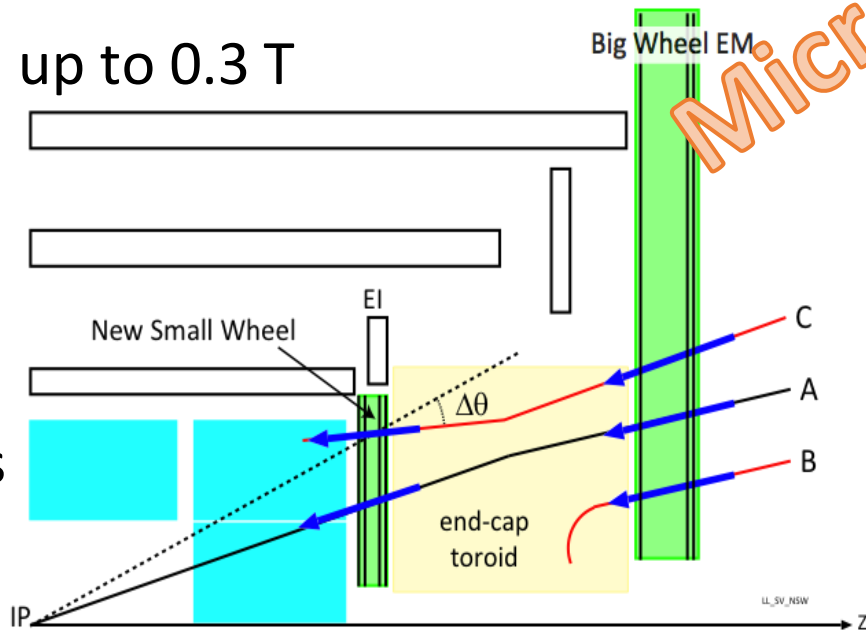
Upgrade of ATLAS muon system in phase-1.

Motivation: reduce fake muon triggers,
precision tracking at high HL-LHC rates

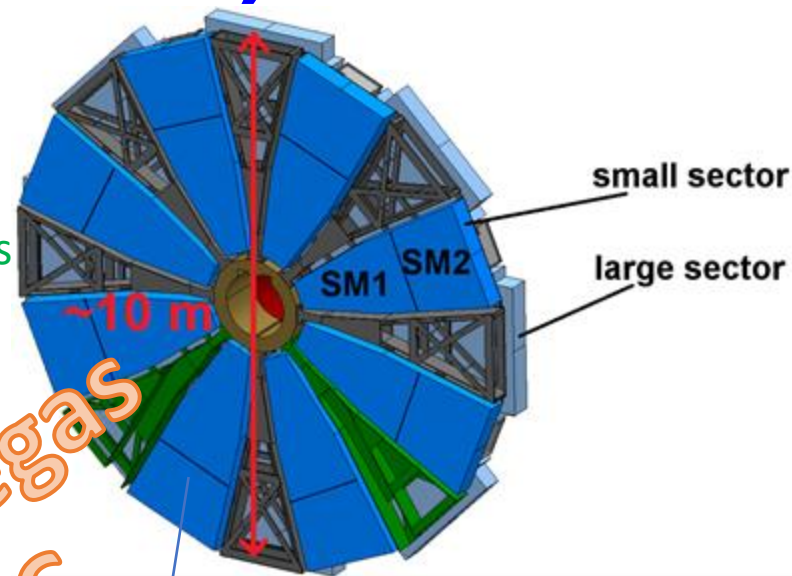
Requirements:

- Rate capability $\leq 20 \text{ kHz/cm}^2$
- Inhomogenous B-field up to 0.3 T
- $\Delta p_T/p_T \sim 15\% \text{ @ } 1\text{TeV}$

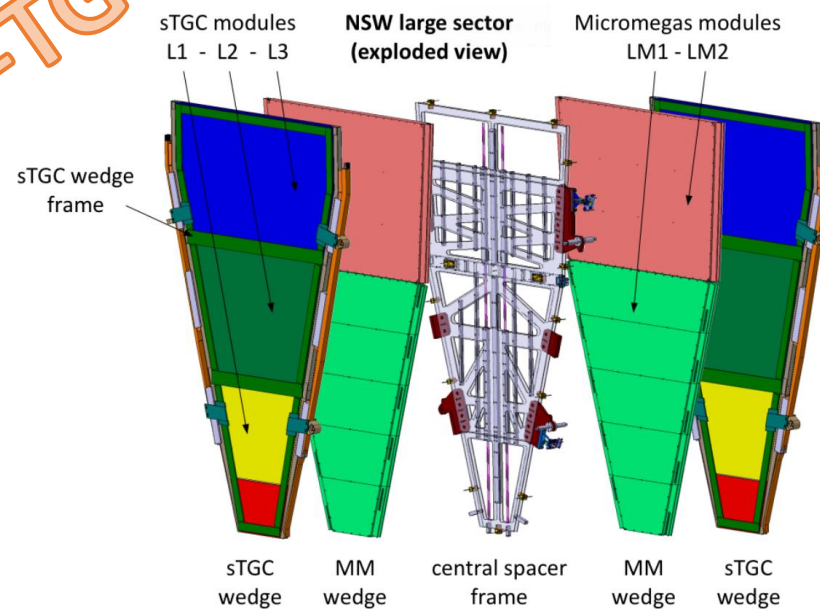
Detector area 2400 m^2 ,
2.1 M readout channels



Small Thin Gap Chambers
(sTGC) for trigger
MicroMegas for tracking
8 + 8 quadruplets



Micromegas
s-TGC

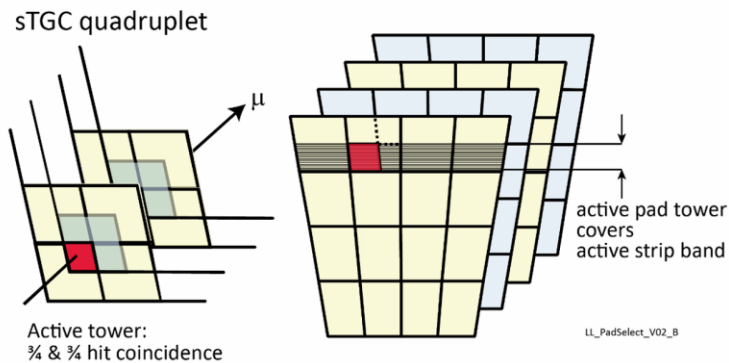


Small-strip Thin Gap Chambers (sTGC)

Multi-wire proportional chambers with resistive cathode and three-fold readout of **wires, pad and strip**

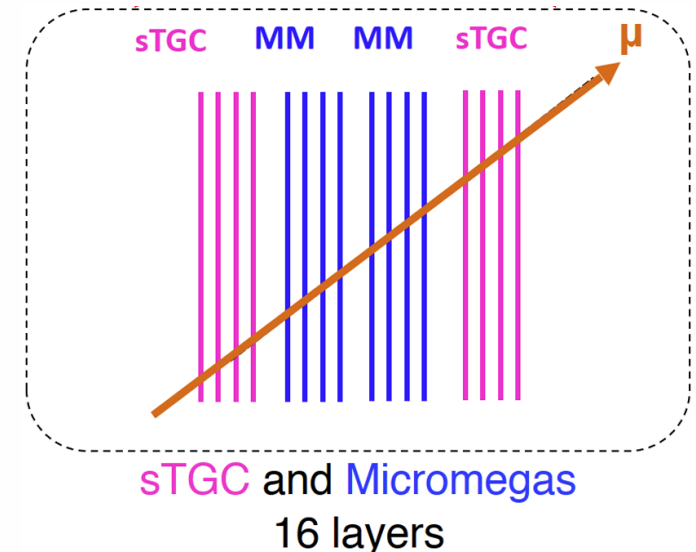
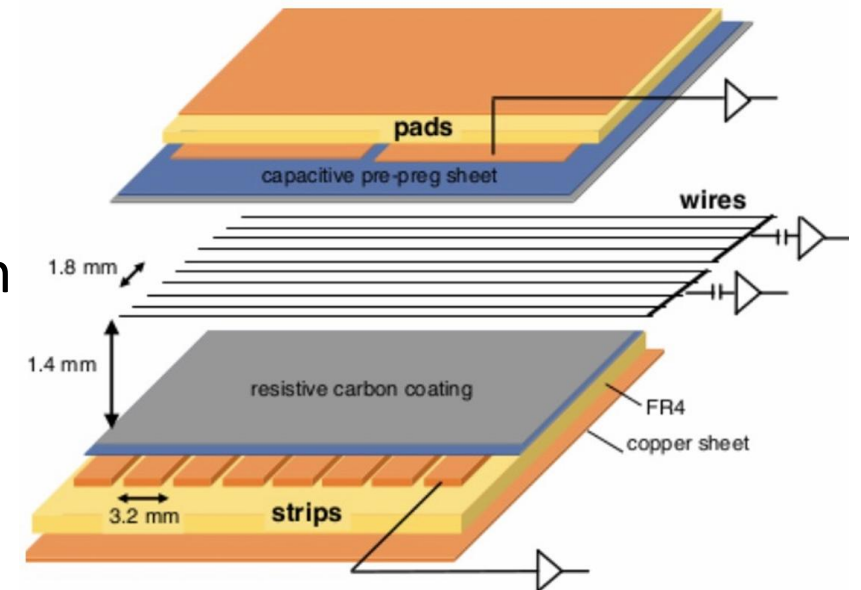
Evolution of TGC technology towards higher rates

- Pad and strip-segmented cathodes covered resistive layer.
→ Lowered surface resistivity for faster charge evacuation
- Strips for high spatial resolution for trigger & track reco
→ smaller pitch (3.2 mm)



Pads provide pre-trigger to select only strips of interest to transmit to Trigger processors

- Wires provide second coordinate → pitch 1.8 mm
- Thin gap (2.9 mm) → good time resolution for BX ID
- Gas mixture: CO₂:n-pentane (55:45)

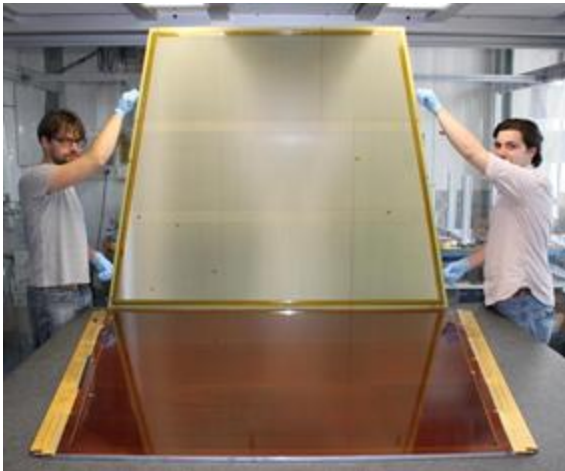


MicroMesh Gaseous Structure (Micromegas)

MPGD. Separating ionisation (5 mm) from amplification (128 μm) -> ion tail suppression -> high rate capability

Go directly from R&D to mass production

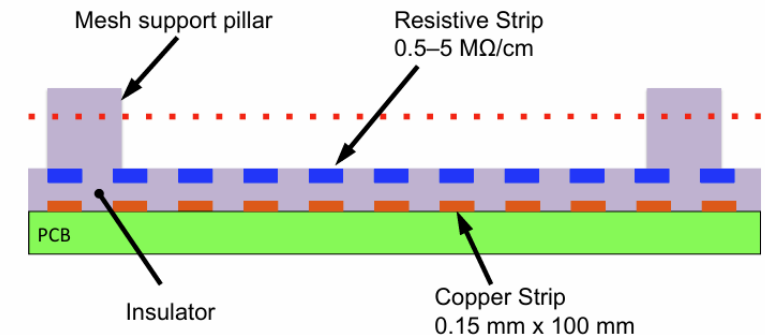
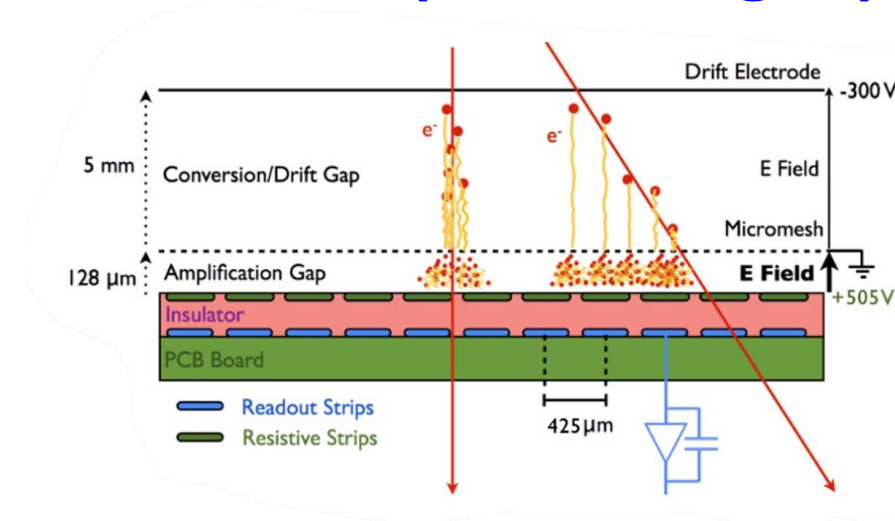
- Large modules of 2-3 m^2 with 4 MM layers each
- Detector area 2400 m^2 , 2.1 M readout channels



- New technology for large-area MM: **amplification mesh integrated in drift panel and separated from readout.**

Advantages: facilitates detector opening, separates PCB production from mechanical production

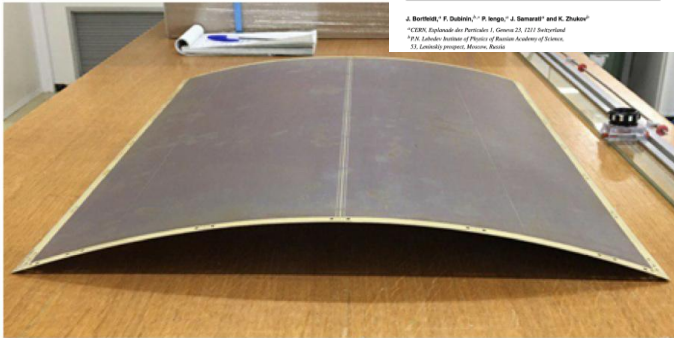
- Developed new scheme with **resistive strips** → strong spark suppression in harsh environment
- Narrow copper readout strips (425 - 450 μm) for high precision



Experience from Construction

MPDG small dimensions , component effects are more important

Panel **material expansion** with humidity to be accounted during production



Knowledge of strip position and deformation crucial for precise tracking

Expansion $\sim 400 \mu\text{m}$ \rightarrow SF for each company developed. After production 4 weeks relaxation in controlled humidity

Resistive paste, three crisis

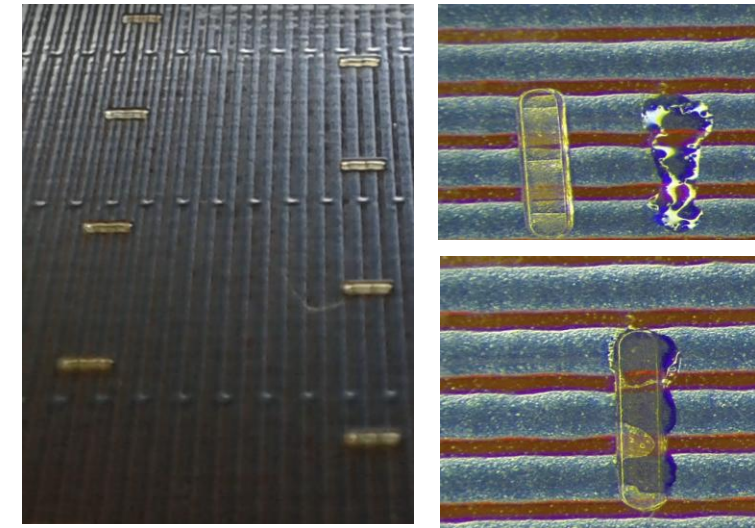
- 1) Resistivity too high, traced to change of solvent
- 2) Low adhesion of resistive strips, traced to insufficient curing at foil printing company
- 3) Producer changed location of paste production without transfer of knowledge.



Pillars, ~ 20.000 pillars/board

Missing single pillar creates sagitta and impacts amplification
Developed repair procedures to recover boards.

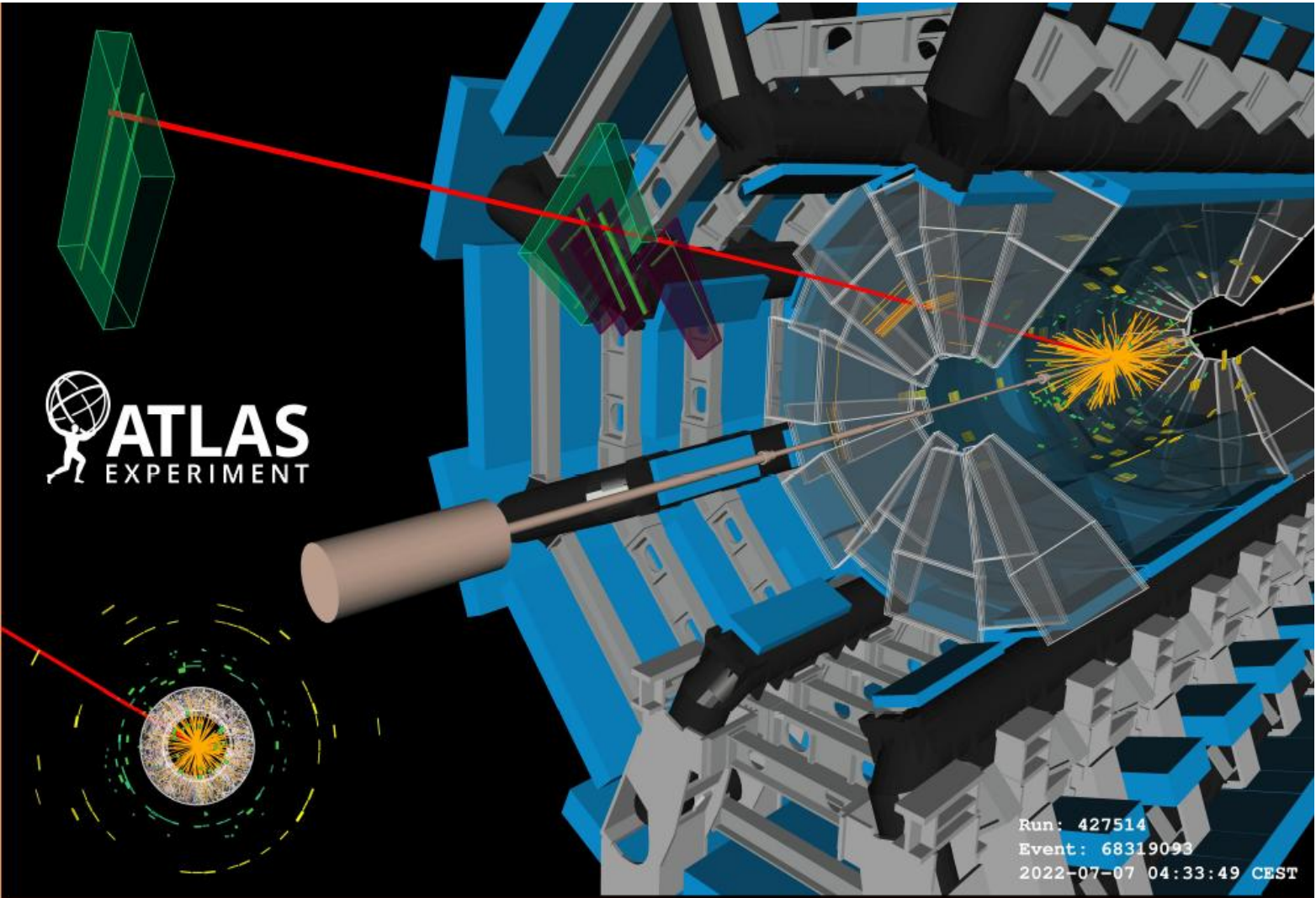
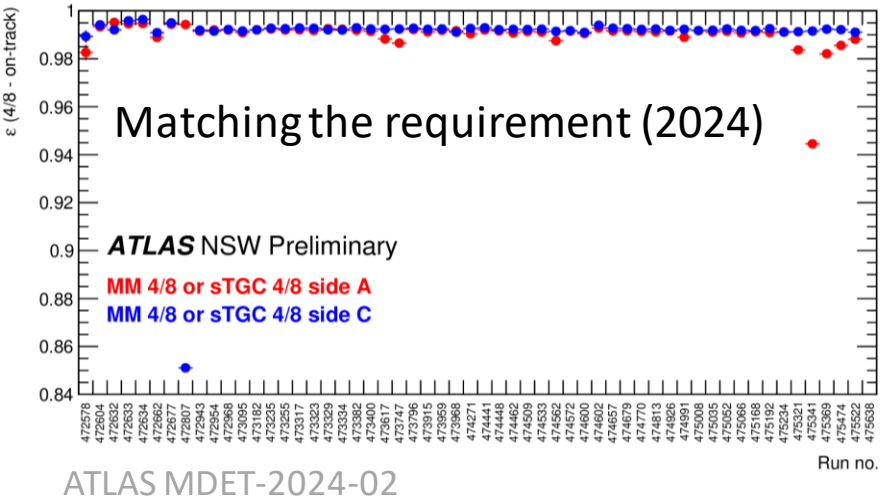
Pillar height $120/128 \mu\text{m}$



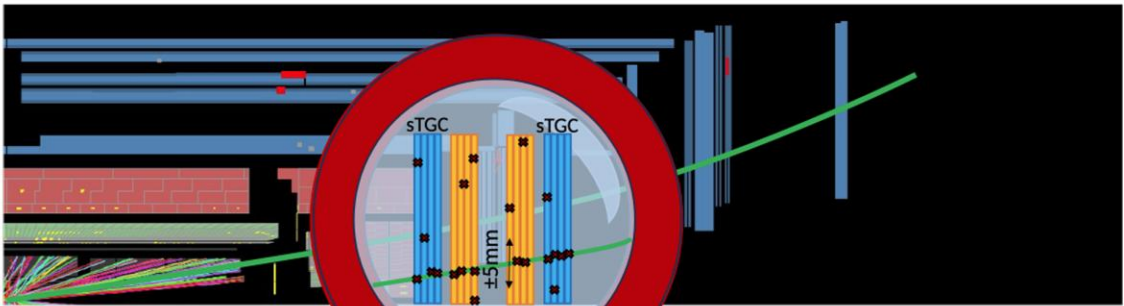
Both New Small Wheels Operate in ATLAS

Commissioning in 2022. Since 2023 fully contributing to ATLAS trigger and physics program

Integrated in ATLAS TDAQ, reconstruction and DCS



Operational Experience (Efficiency)

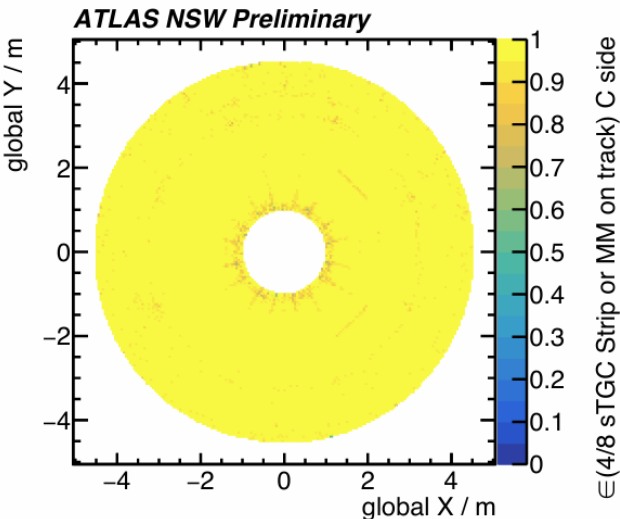
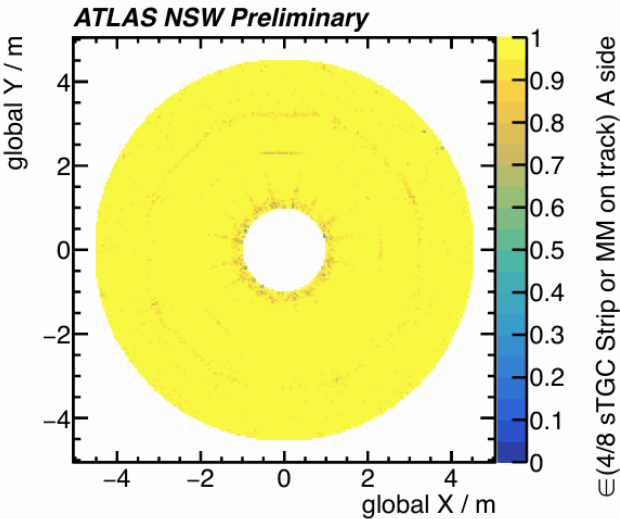
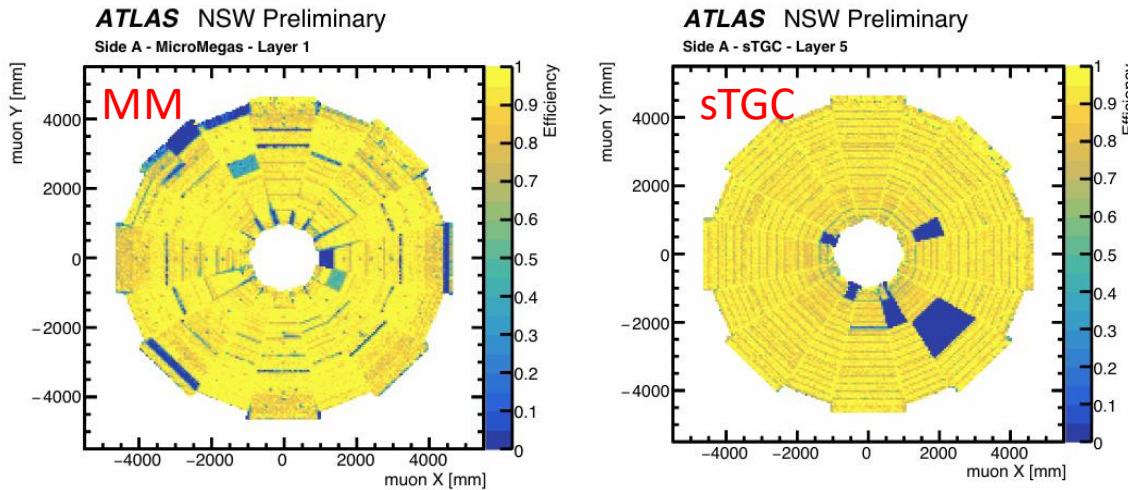


Combined efficiency **>95%** thanks to high redundancy
(average 4/8 layers either MM or sTGC)

Muon selection:

- Require muon tracks with $p_T > 15$ GeV
- Reconstructed muons as combined (ID track + MS track combined) or standalone (MS track only)

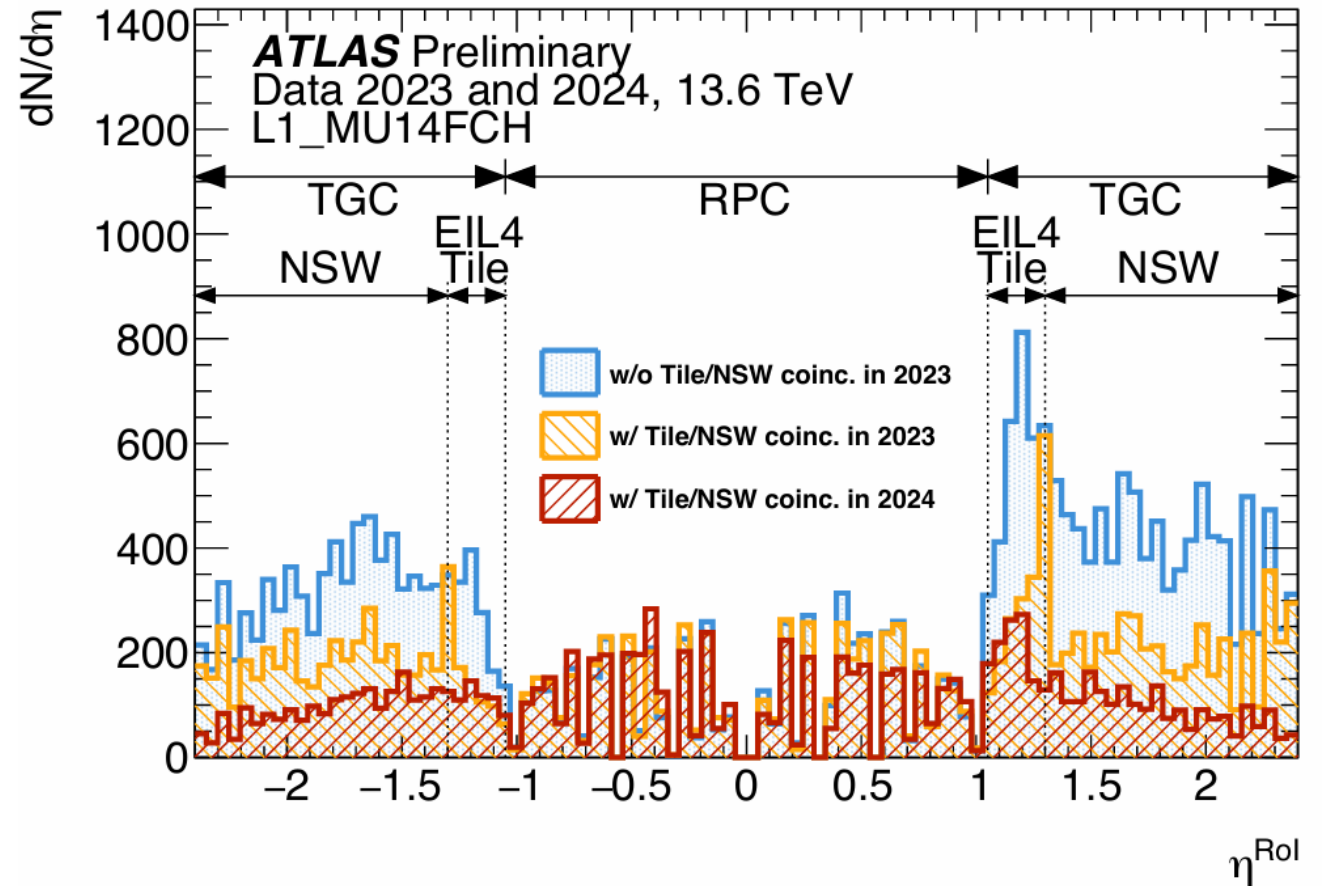
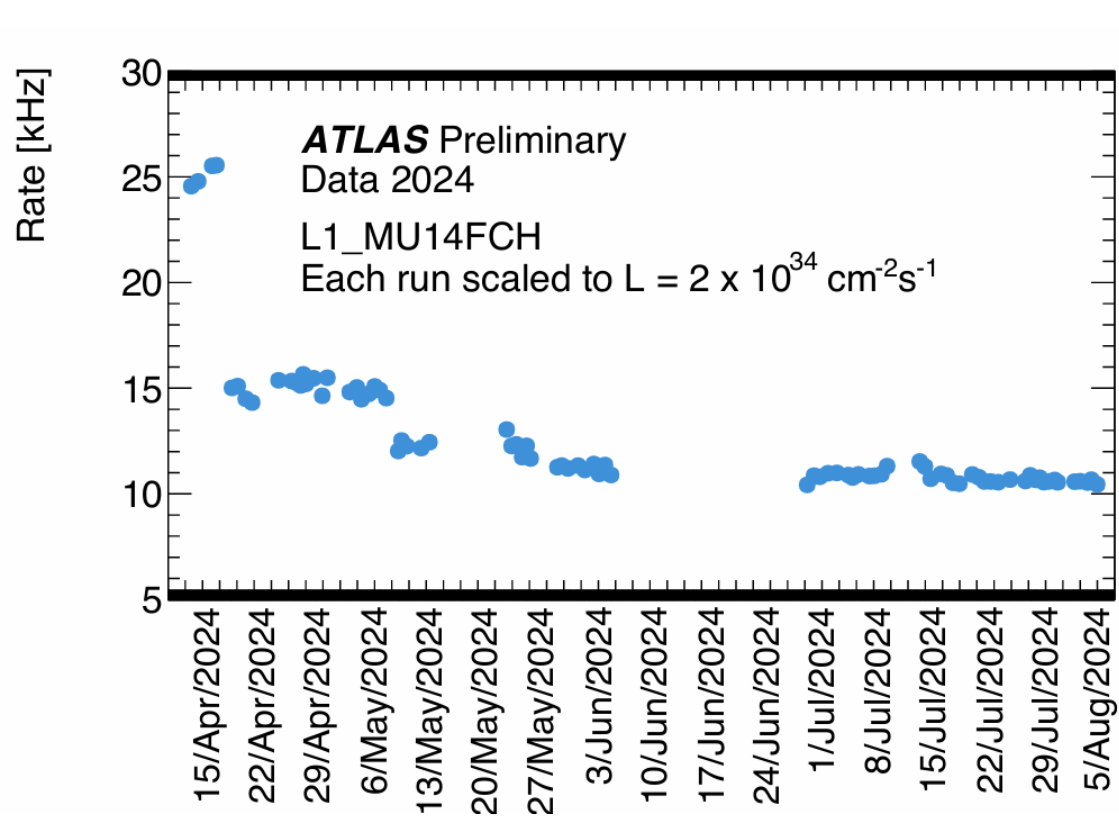
Single layer efficiency. Inefficiencies in some regions due to HV/LV/readout issues during data taking.



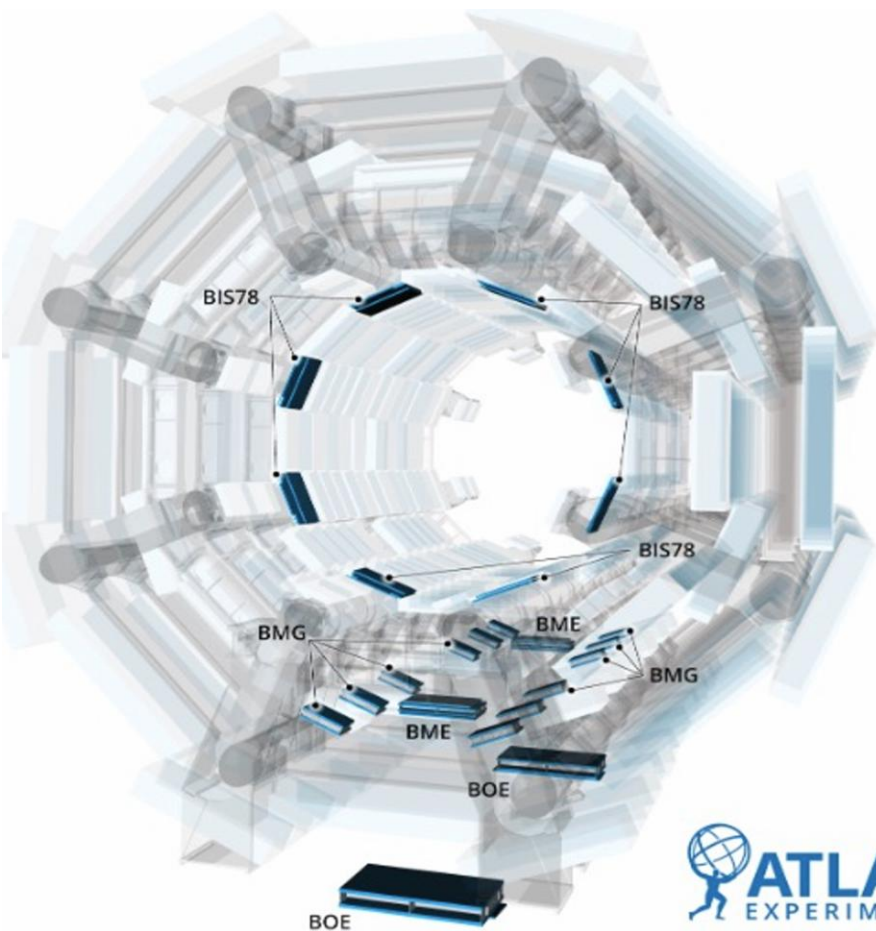
4/8 MM
or
4/8 sTGC
(on-track)

Trigger Goal is Achieved

In total coincidence of Big wheel, tile calorimeter and NSW (all sTGC + MM sectors)
about halved the primary L1 muon trigger rate



New Generation ATLAS RPC

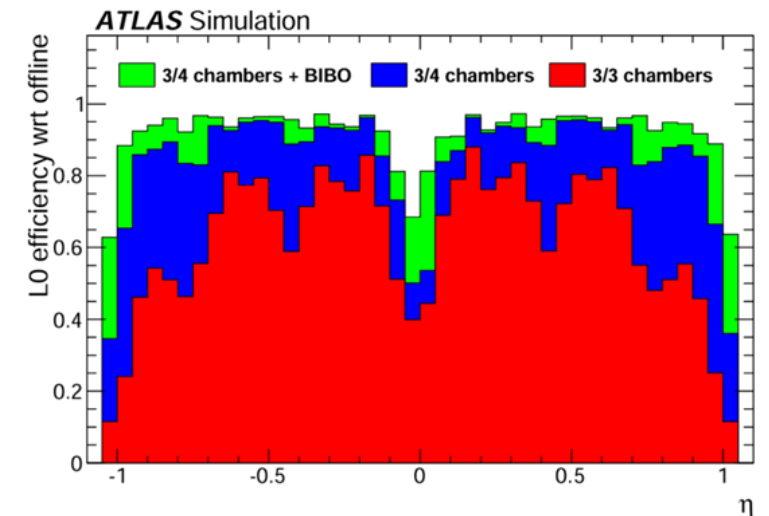
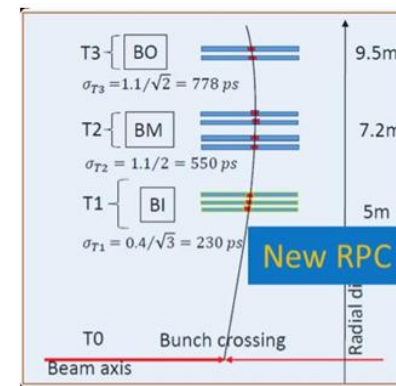


Status: production started in 2023.
Two new production centers
(Munich, Hefei China)

For HL-LHC upgrade barrel inner region (BI) with ~ 300 new gen. RPC triplets to improve trigger redundancy ($6 \rightarrow 9$ layers)

New generation RPC:

- Thinner electrodes (1.4 vs 1.8 mm), lower resistivity (500 vs 320 k Ω /cm)
- Smaller gas gap (1 vs 2 mm) for improved time response (0.4 vs 1 ns)
- New FE electronics with better sensitivity (1-2 fC), improved time resolution (250 ps)



Improved RPC rate capability

Motivation similar to NSW: **reduce fake triggers** in barrel-EC transition

Summary

- Legacy ATLAS/CMS muon systems work very well
- Need to reduce F-gases because of high GWP
- No need for full system replacement. Upgrades to strengthen weakly instrumented areas, improve trigger purity at HL-LHC
- CMS upgrade of very forward muon region with Triple-GEM detectors and improved RPC.
- ATLAS NSW upgrade in the forward regions and additional (thin) RPCs in barrel.
- Largest MPGD systems ever built.




Backup

Experience & Upgrade DT Electronics

Concept of tracking trigger impacts needed latency and rate

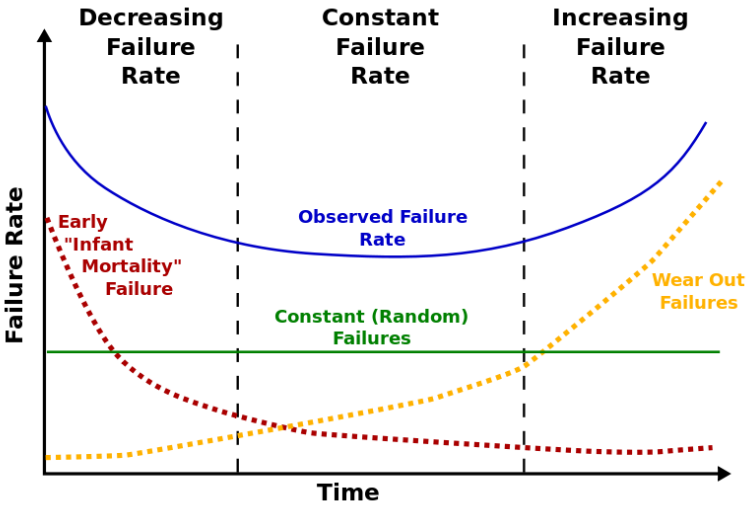
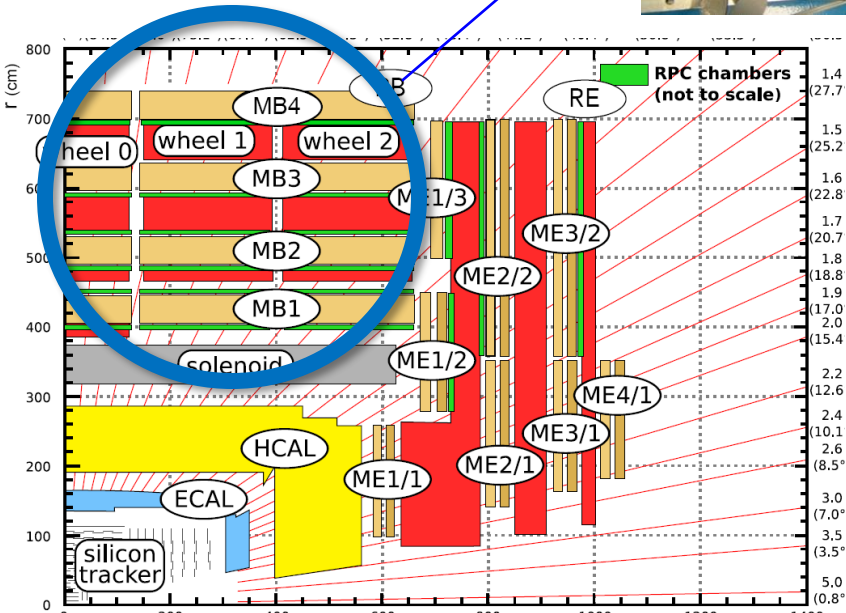
Level 1 Latency from 3 μ s \Rightarrow 10 μ s

Level 1 Rate from 100 kHz \Rightarrow 1 MHz

L1 rate needs replacement of the DT on-chamber electronics 



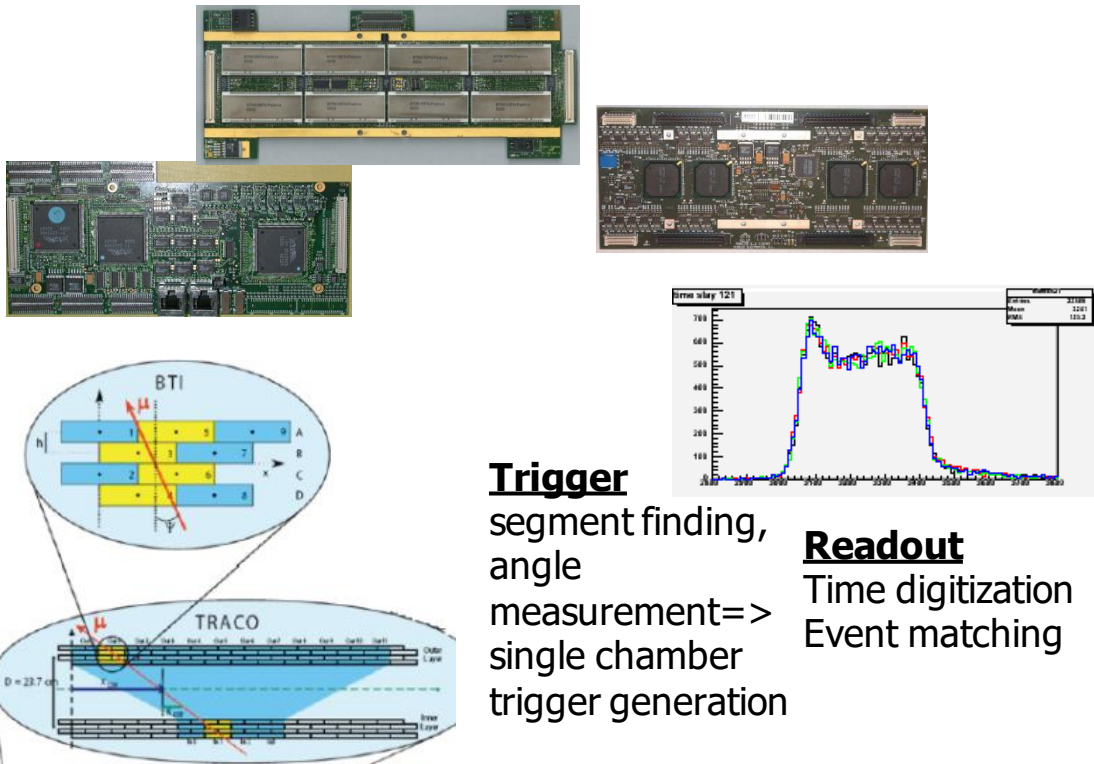
Another argument: electronics is old. Wear-out failure may increase



Upgrade of DT on-chamber electronics

Legacy Minicrates

- Highly integrated and complex system
- Many boards with various ASICs for specific tasks
- Trigger primitive generation performed inside each chamber
- Filtered information sent to counting room



Trigger
segment finding,
angle
measurement=>
single chamber
trigger generation

Readout
Time digitization
Event matching

Phase-2 Minicrates

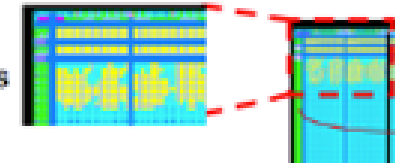
- On-chamber electronics performs time digitization of all chamber signals
- Digital information sent through optical link to counting room
- Complexity is brought into the counting room



Radiation tolerant FPGAs
which perform 1 ns time
digitization (no filtering)

GBT link for
data
forwarding

Zoom of first
4 TDC channels



*** Allows readout at 1 MHz Level 1 and 20 us latency**

*** Trigger primitive generation:**

- maximum chamber resolution
- room for pt resolution increase

Eco-friendly Gas Mixtures

Finding alternatives

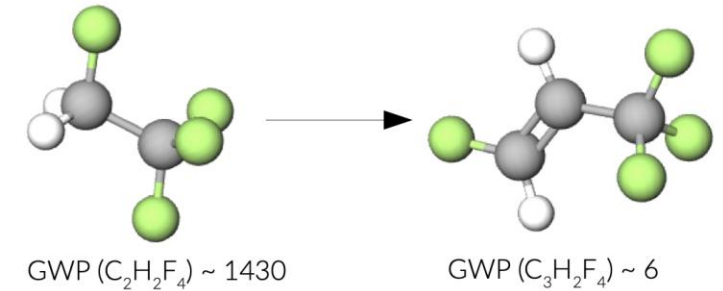
Several gases with **low GWP** scrutinized with:

- Good F/C ratio that plays significant role for Si etching
- No hazardous characteristics (toxic, flammable, etc.)
- Relative short molecules (long chains tend to polymerize, i.e. may cause anode/cathode ageing)

→ **not so many good candidates found!**

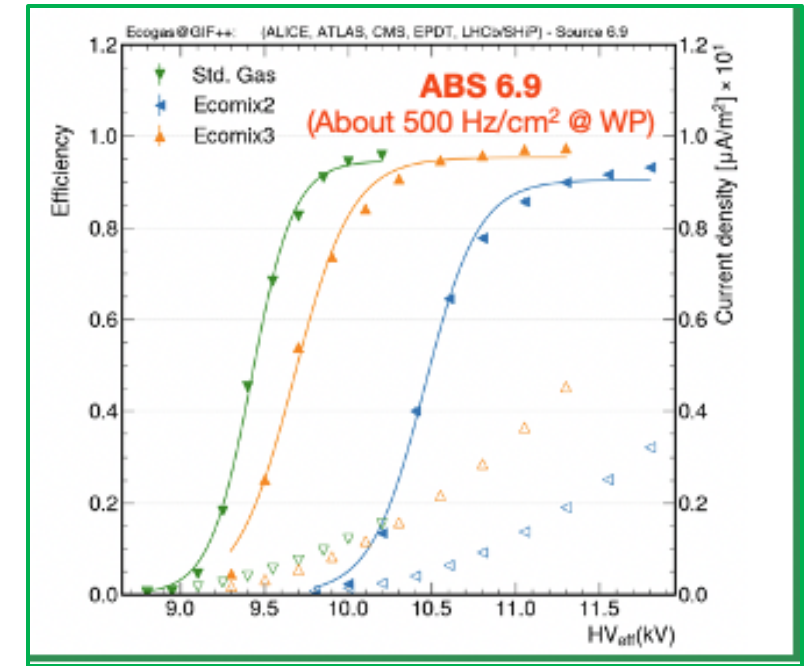
• HFO1234ze Accelerated longevity studies with CSC:

- + no gain degradation up to 1.2 C/cm^2
- - significant increase in dark current after 0.6 C/cm
- Significant modification of the anode wire surface with formation of tungsten oxide
- **RPC EcoGas@GIF++ collaboration** tested mixtures of HFO (25 – 45%) + CO_2 (50 – 70%) + iC_4H_{10} (4%) + SF_6 (1%)



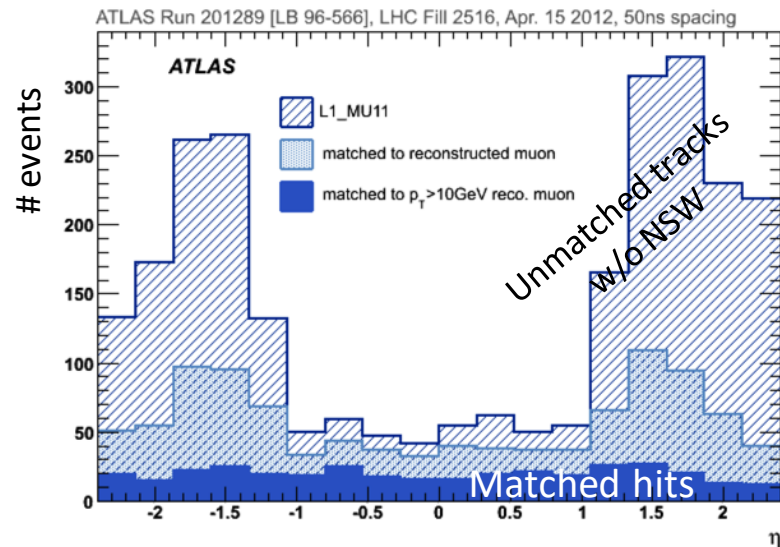
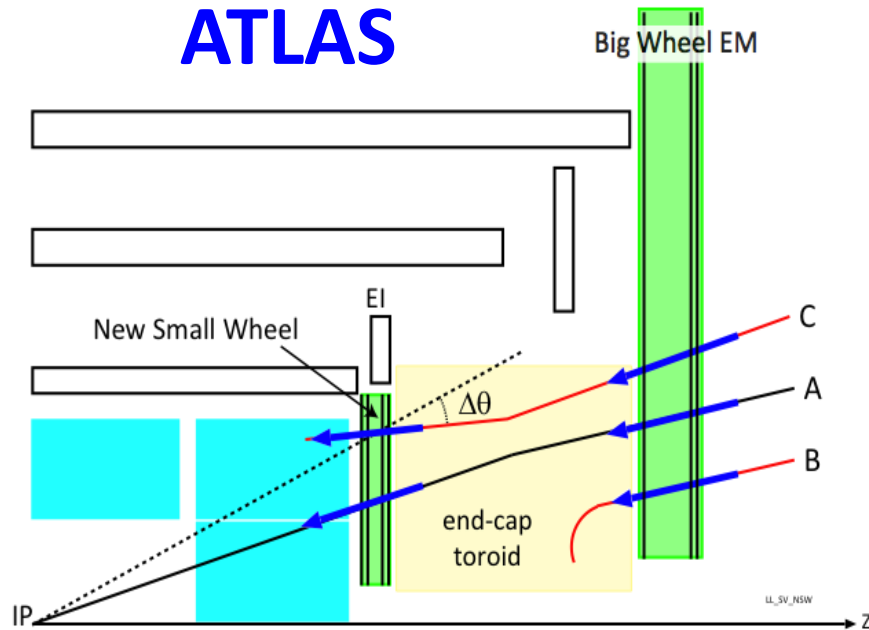
HFO1234ze

RPC chambers without wires. Work in streamer or avalanche mode



Muon Endcap Trigger Challenge

ATLAS



Goal: **efficient** muon triggering at increasing luminosities

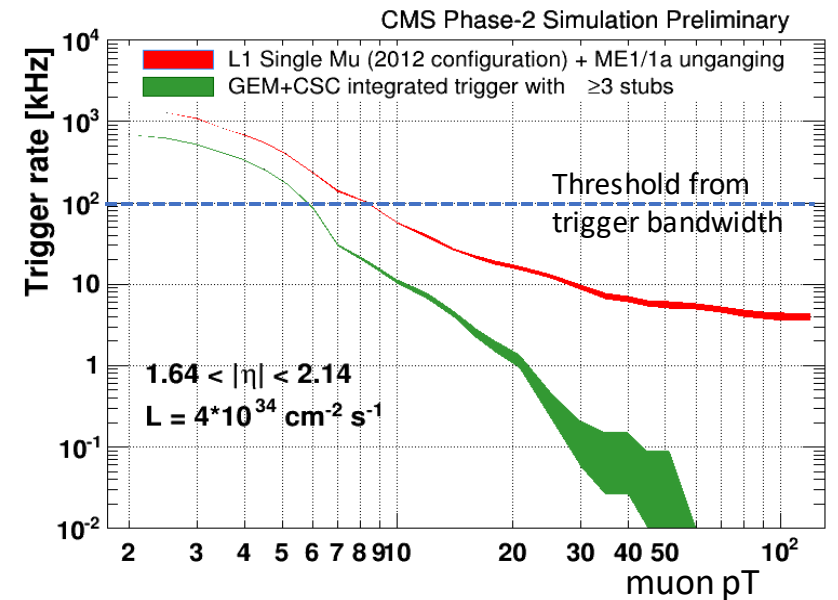
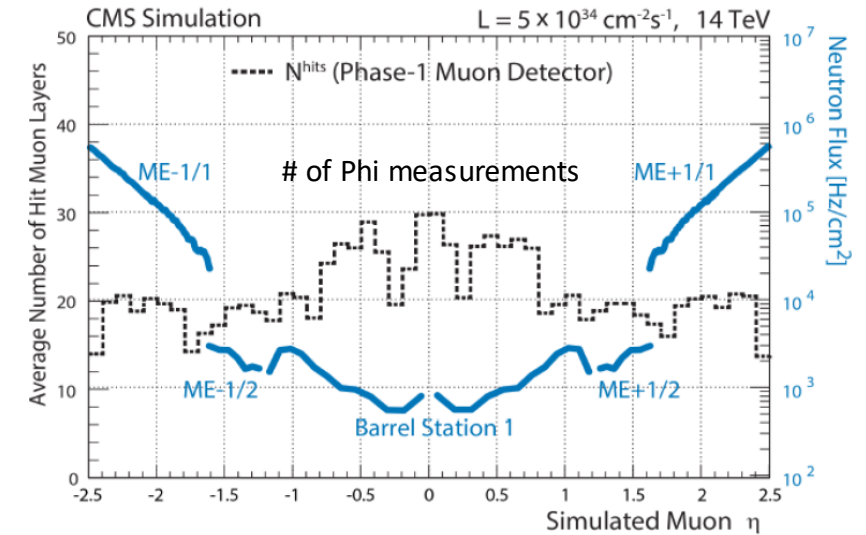
→ remove fake and unmatched low momentum muons

L1 trigger rate to stay within bandwidth and keep threshold



add more measurement points

CMS

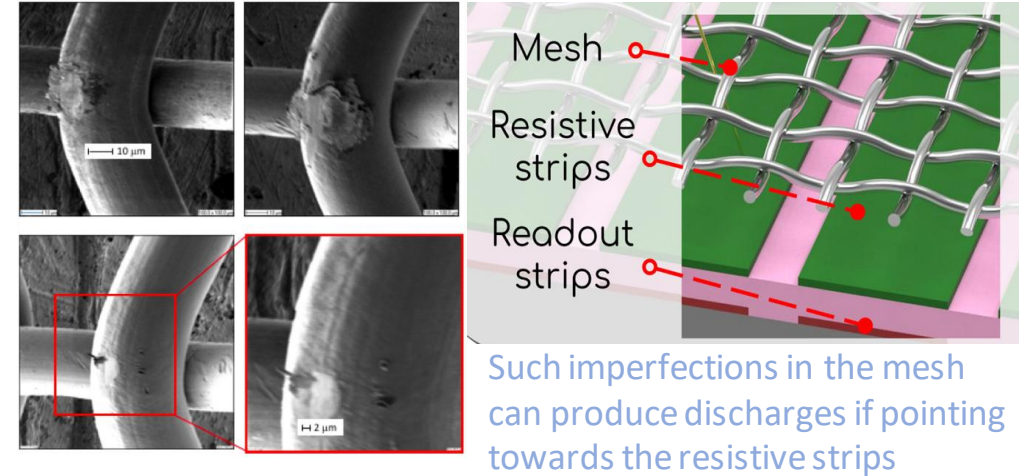


ATLAS Micromegas HV Stability

Cleaning is essential (brushing, washing, drying) to remove any dirt and solid deposits on readout boards.

Implement mesh polishing with fine sandpaper removing mechanical imperfections.

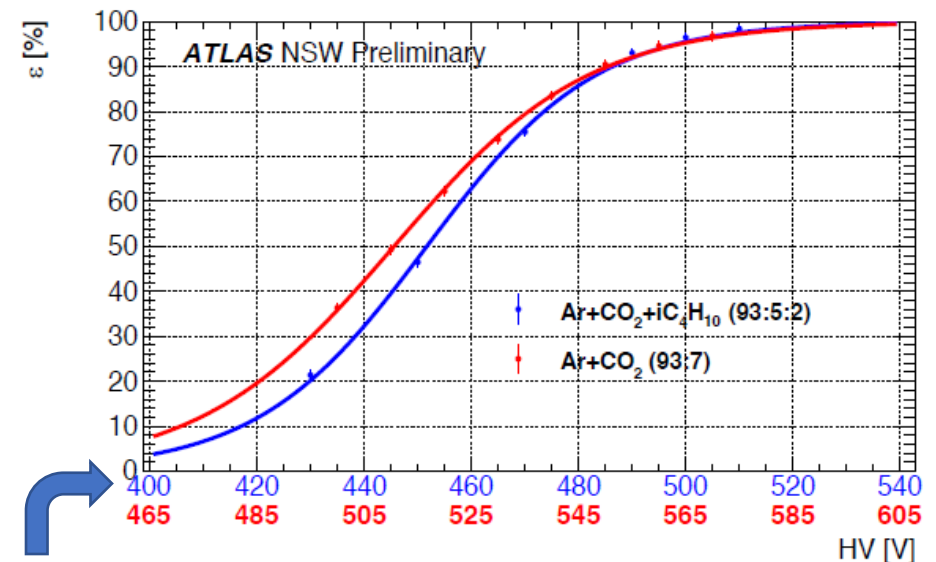
→ Find microscopic imperfections on $O(m^2)$ surfaces



Gas mixture to reduce HV

Foreseen mixture $Ar:CO_2$ 93:7 at $HV_{RO} = 570$ V is a low quenching mixture

Added iC_4H_{10} to reduce amplification voltage
to 520 V = better stability, higher gain, less sparks



Lower HV with $Ar:CO_2:Iso$ 93:5:2

GEM Discharge Protection

MPGD issue: due to small distance, formation of **spark** can easily be followed by **discharge** and damage detector or readout

Large GEM foil = large capacitance = large reservoir of energy to feed the discharge

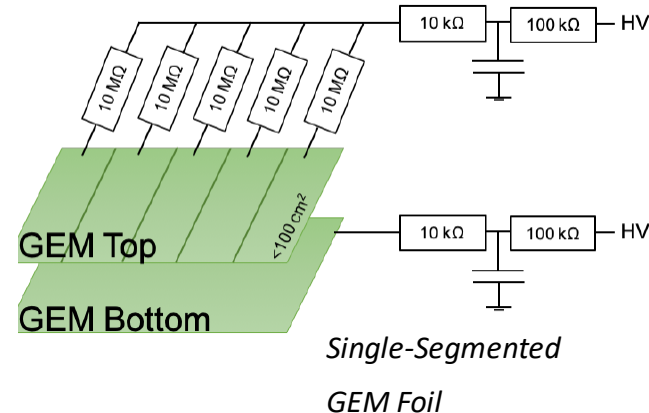
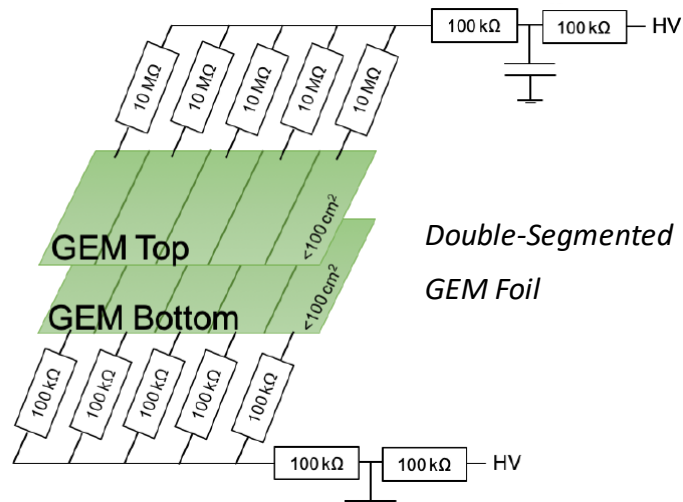
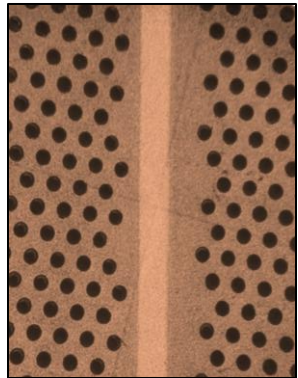
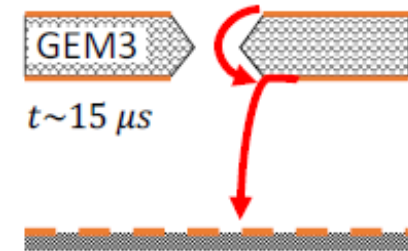
Discharge probability

Addressed by multiple GEM stages with lower HV/stage

x

Discharge propagation

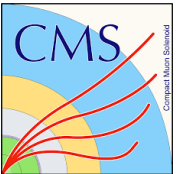
Addressed by foil segmentation and resistors



GE1/1 single-segmented foils for all 3 stages

GE2/1, ME0 double-segmented GEM1,2.
Single-segmented GEM3

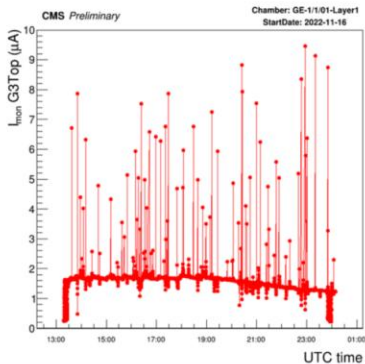
Separate HV sectors. If one fails, the rest continues to work.



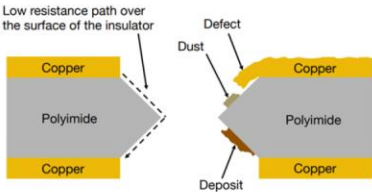
GE1/1 & GE2/1 Operational Experience

Installed GEM detectors: full GE1/1 system installed since LS2 and operational in regular CMS DAQ during Run-3. Four GE2/1 chambers for tests & demonstration.

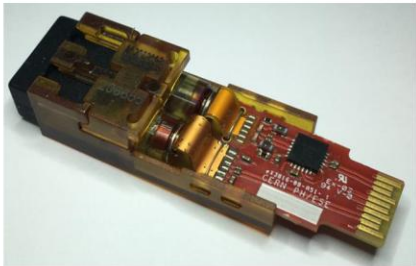
Issues summary



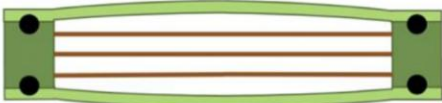
DISCHARGES
Impact:
HV instability, short circuits in GEM foils, reset and dead channels in electronics



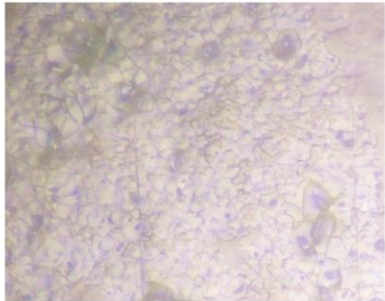
SHORT CIRCUITS IN GEM FOILS
Impact:
Inefficient areas, lower voltage applied to the whole foil



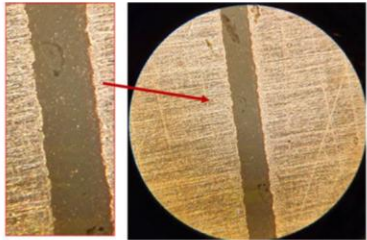
VTRx instability
Impact:
Areas of electronics (part or full detectors) not read



PCB bending
Impact:
Local difference in electric fields (and so lower efficiency). Degradation of hit time of arrival (and so time resolution)



Non passivation of PCBs copper
Impact:
Oxidation signs

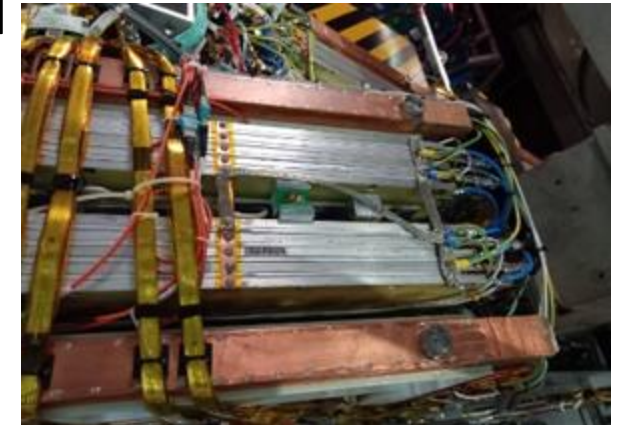
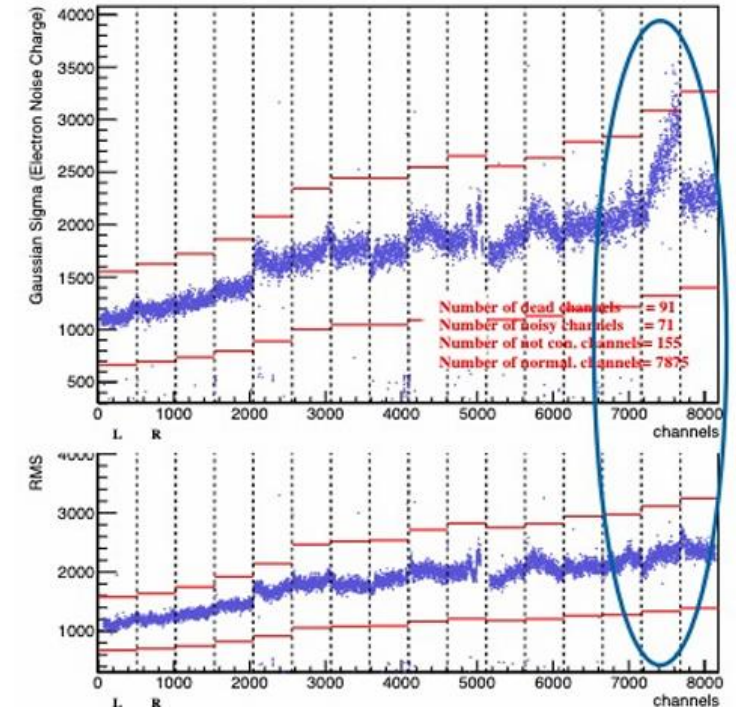


Copper dust on GE2/1 PCBs
Impact:
Generation of short circuits

Issue during MM Commissioning

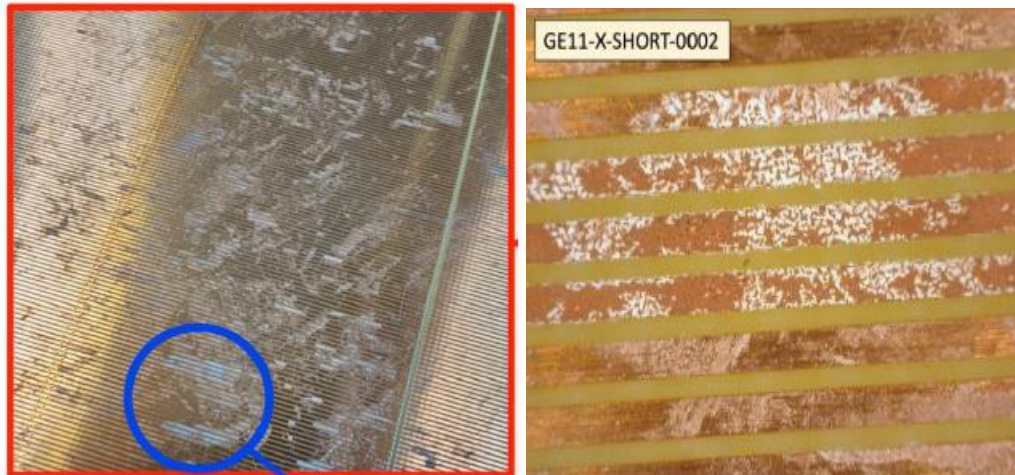
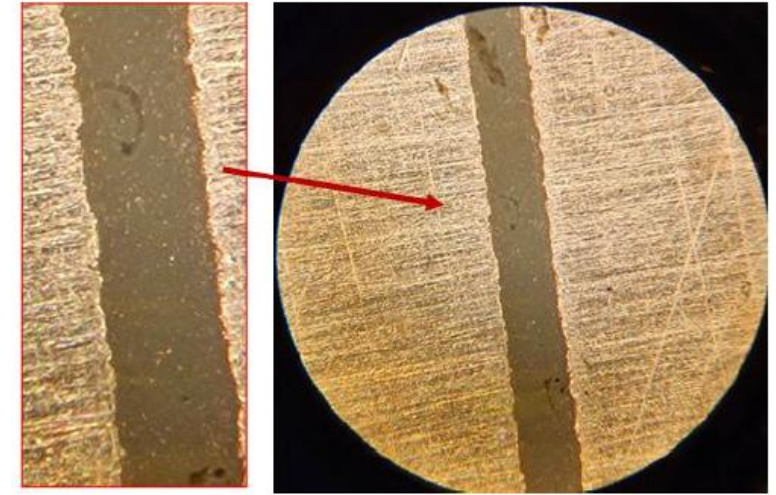
Large system → many problems,
complex system → tricky problems

- Observed **increase of electronic noise** on both sTDC and Micromegas after mounting on wheel on surface
- Identified to mostly come from LV power supply and sub-optimal grounding
- **Actions taken, solved the problem on surface**
 - Refurbishment of LV power supply (additional filters added)
 - Modification of grounding scheme and improvement of detector ground
 - Addition of Faraday cage on FE elx boards
- After installation in ATLAS discovered a remaining high noise on longest Micromegas strips, correlated with magnetic field → masked ~% channels



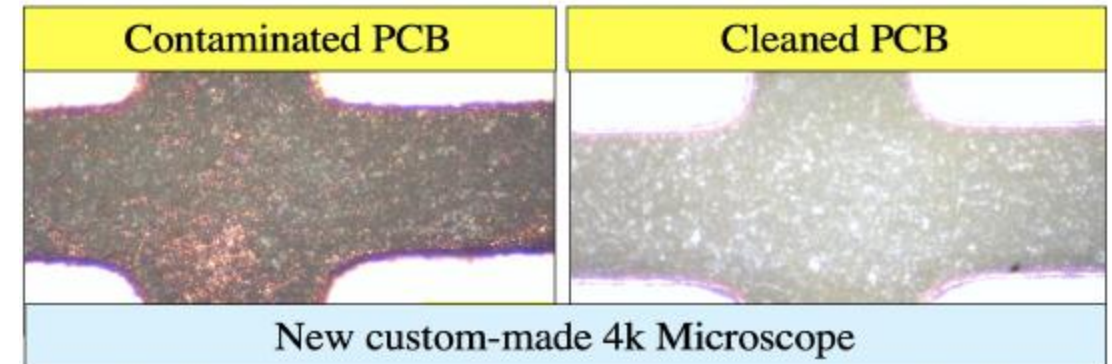
Passivation of GEM PCBs

- PCB is a critical component that hosts the Drift electrode, the RO strips and forms the main body of the modules
- Discovered summer 2023 that PCBs were not passivated → copper dust in detectors
- Signs of **oxidation** in irradiated area of GE1/1 ageing detector

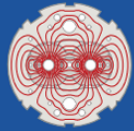


GE2/1 issues discovered during QC. Interrupted mass production. Five demonstrator chambers operate in CMS. Behaviour is monitored.

- **Developed cleaning procedure**
- Adapted QC protocol (microscopic inspection of RO board)



- LHC Run-3 on-going reached 300 fb⁻¹ already before the LS3 for the upgrade to HL-LHC
- EYETS at the moment till mid-March 2025, stable beam collisions expected on May 2025
- Goal is to reach the target for the delivered luminosity before the major upgrade during LS3



LHC / HL-LHC Plan

